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(54) **TOP EMISSION MICROLED DISPLAY AND
BOTTOM EMISSION MICROLED DISPLAY
AND A METHOD OF FORMING THE SAME**

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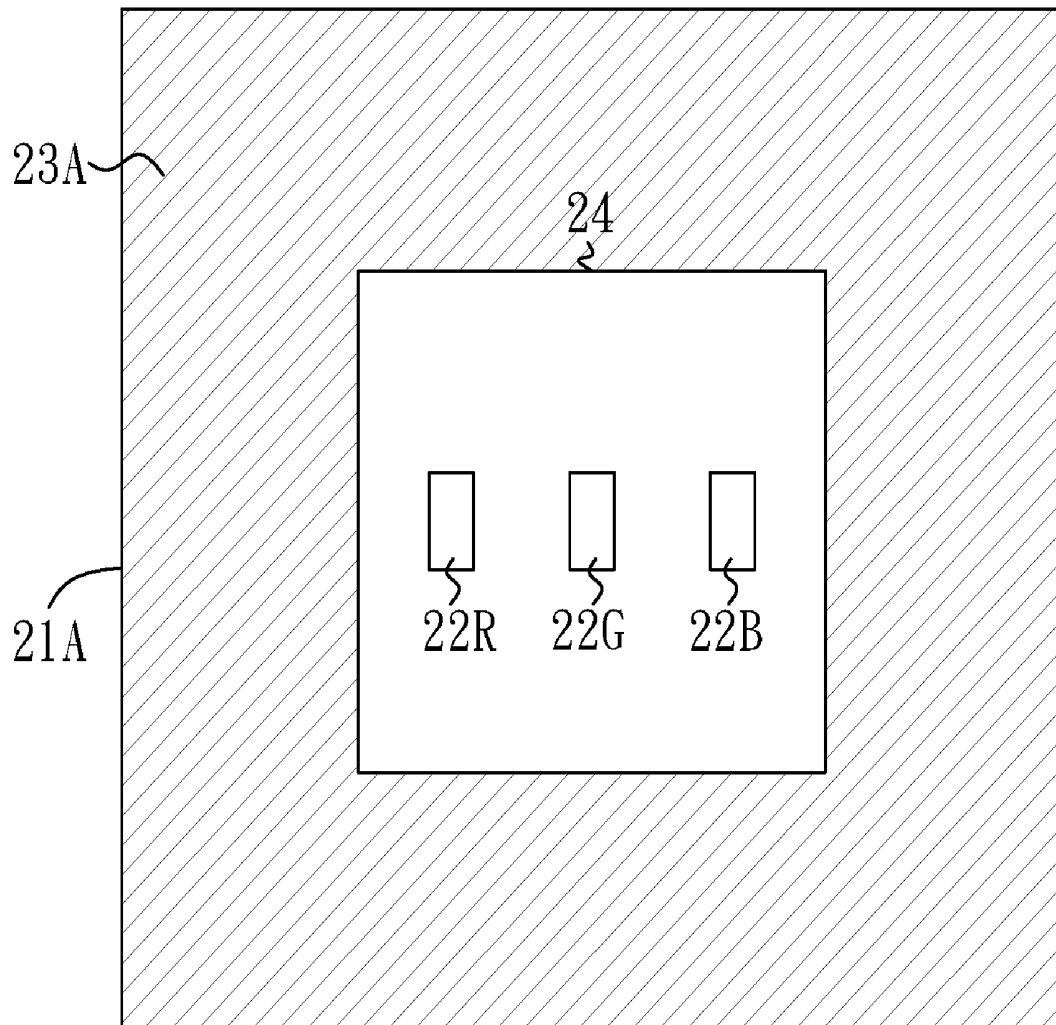
Related U.S. Application Data

(63) Continuation of application No. 16/128,255, filed on
Sep. 11, 2018.

(57) **ABSTRACT**

A microLED display includes a first main substrate, microLEDs disposed above the first main substrate, a first light blocking layer disposed above the first main substrate to define emission areas, a light guiding layer disposed in the emission areas, and a plurality of connecting structures disposed in the emission areas respectively and electrically connected with the microLEDs.

300



100

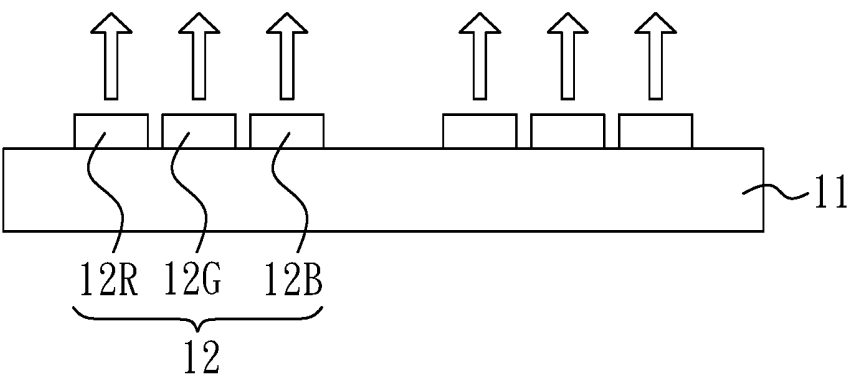


FIG. 1

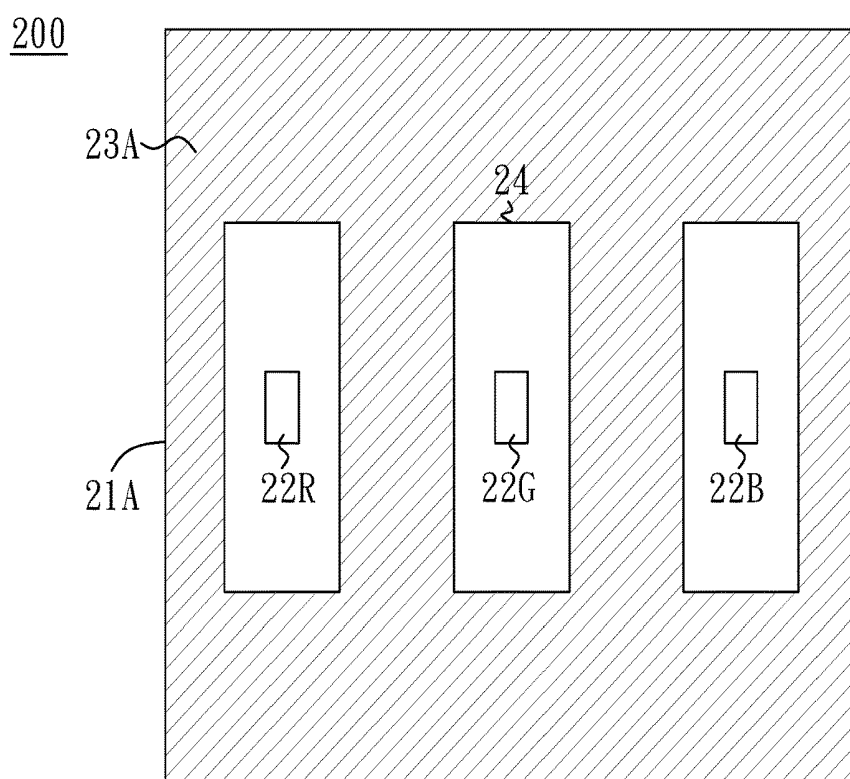


FIG. 2A

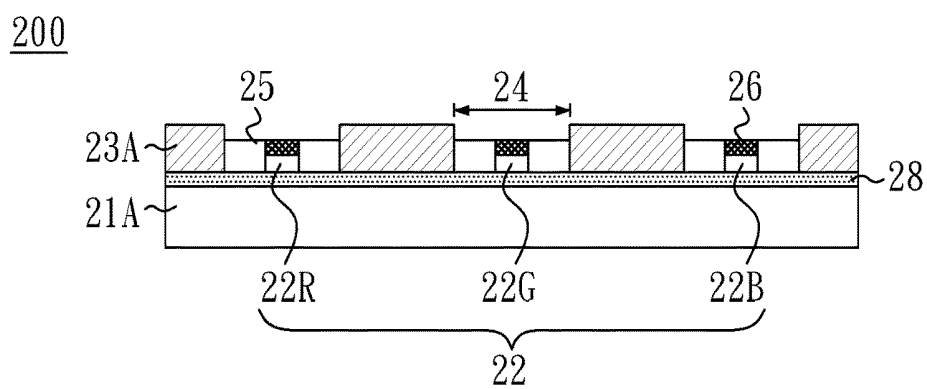


FIG. 2B

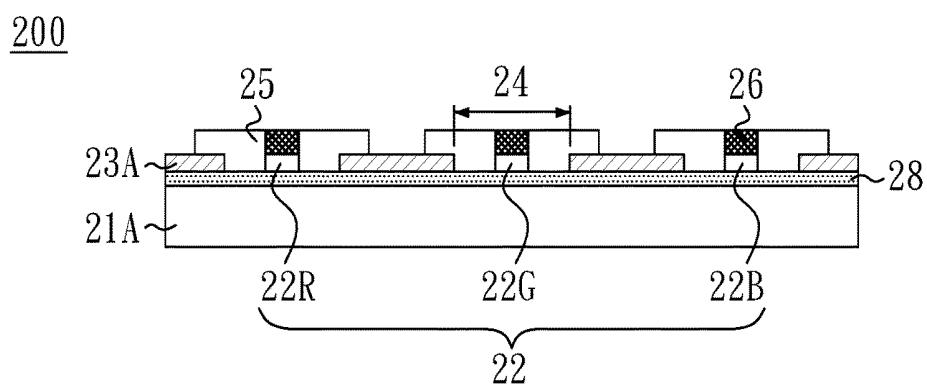


FIG. 2C

200

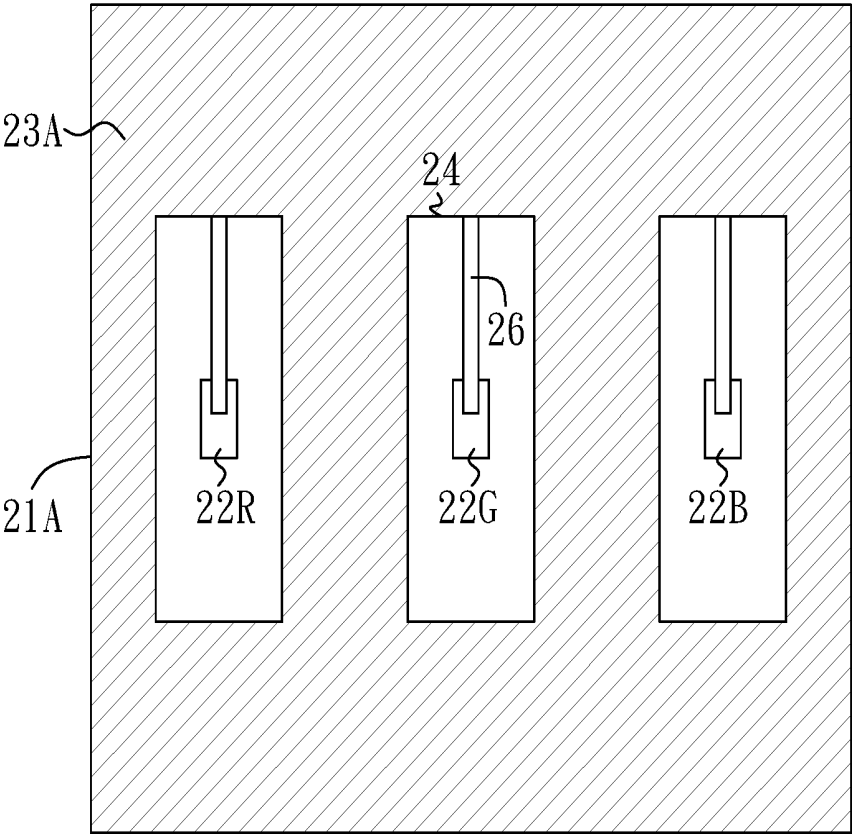


FIG. 2D

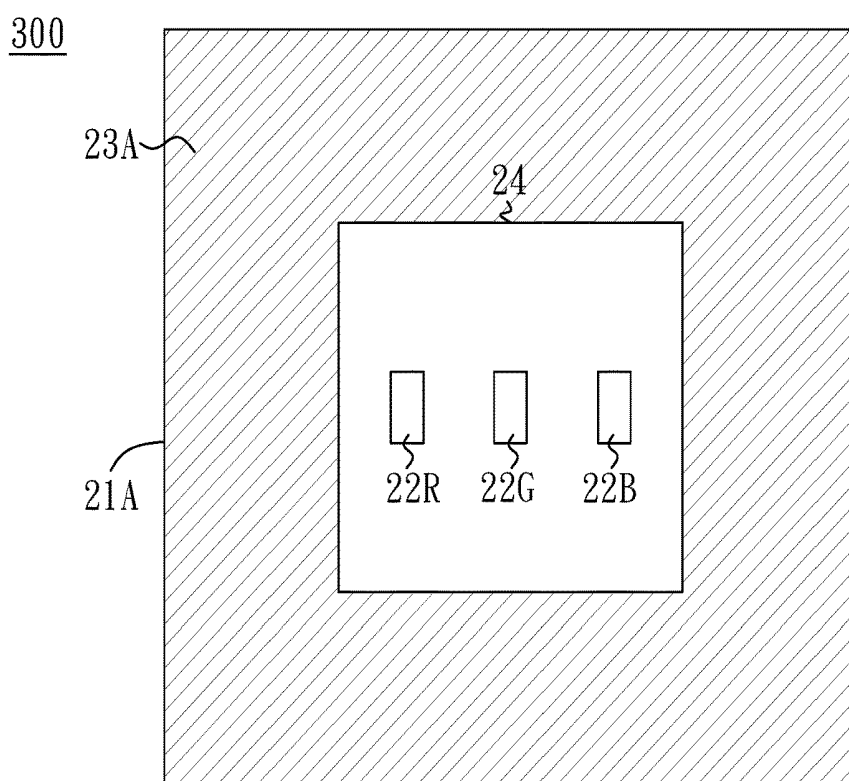


FIG. 3A

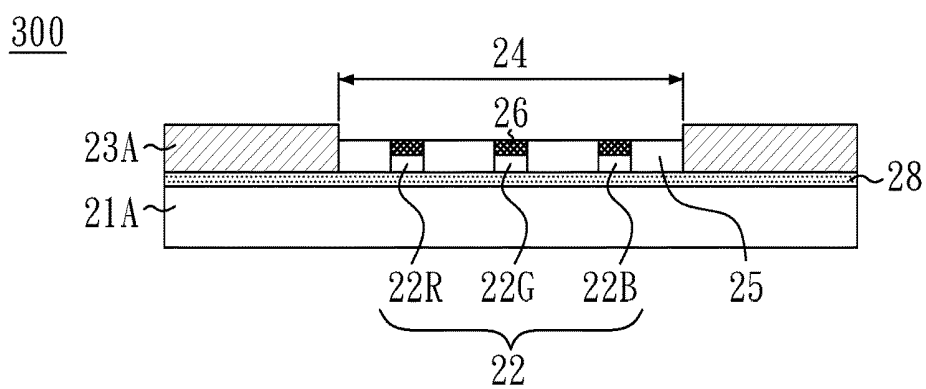


FIG. 3B

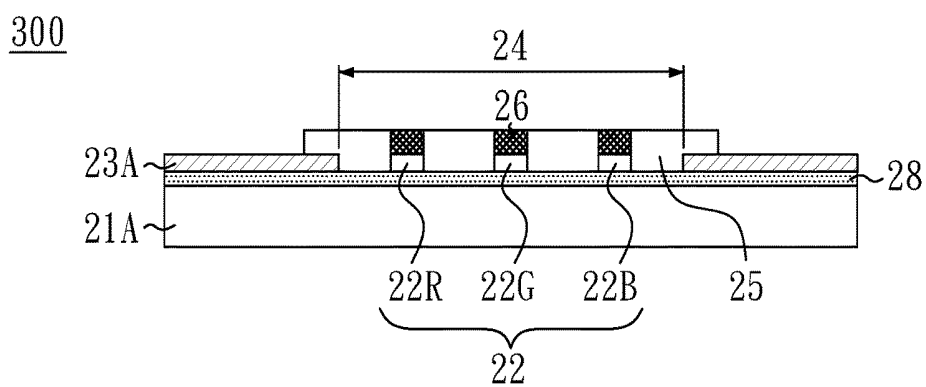


FIG. 3C

300

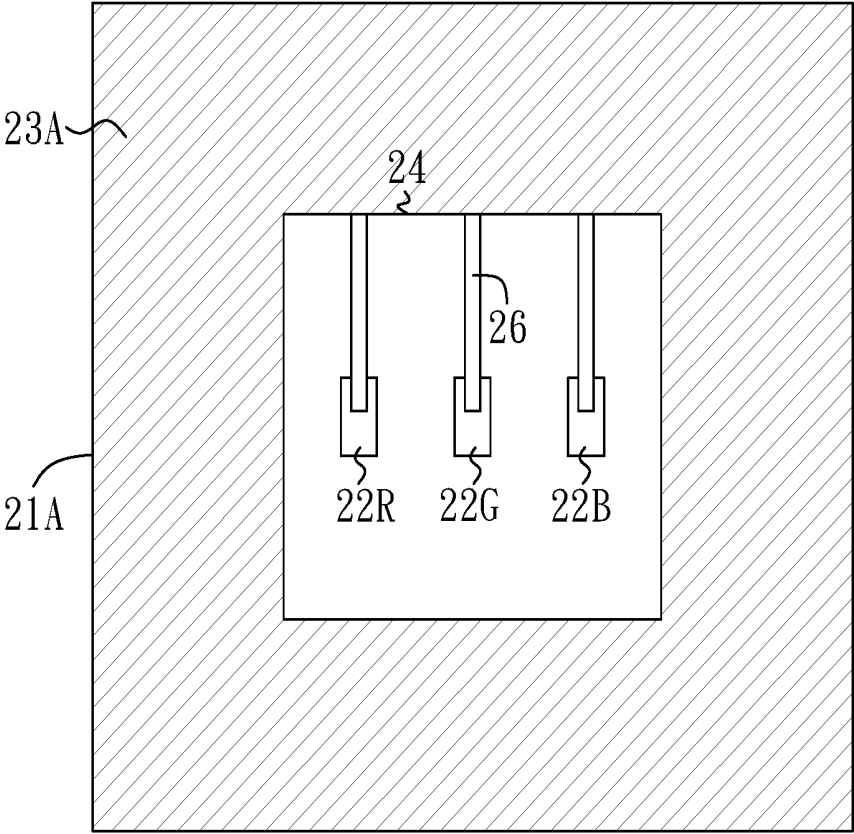


FIG. 3D

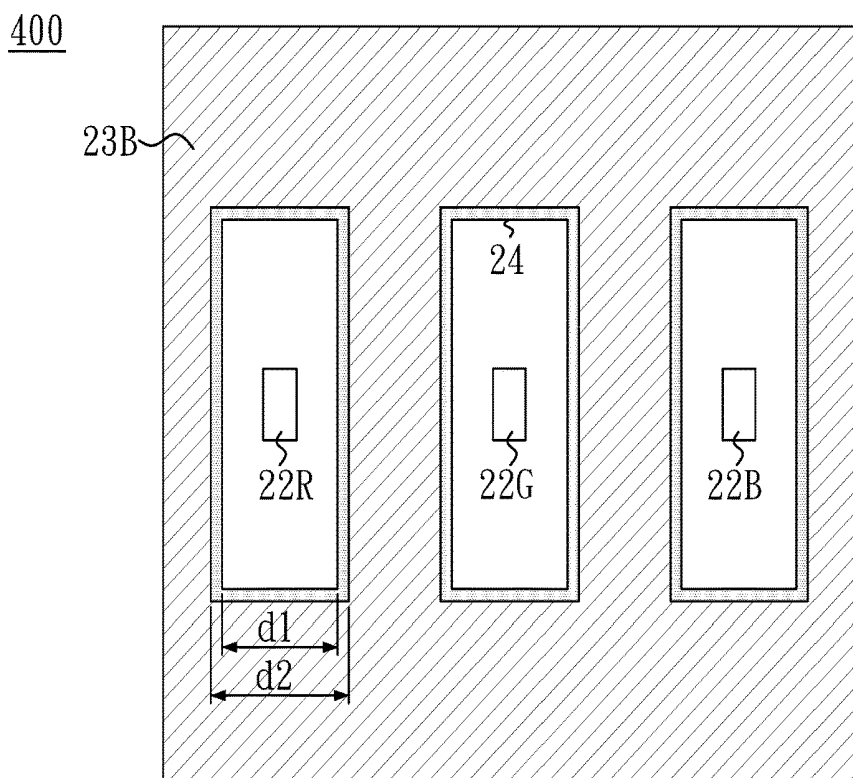


FIG. 4A

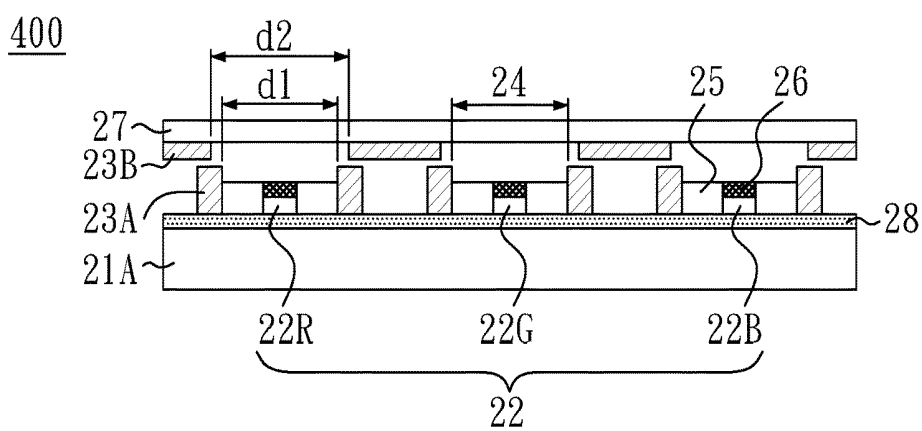


FIG. 4B

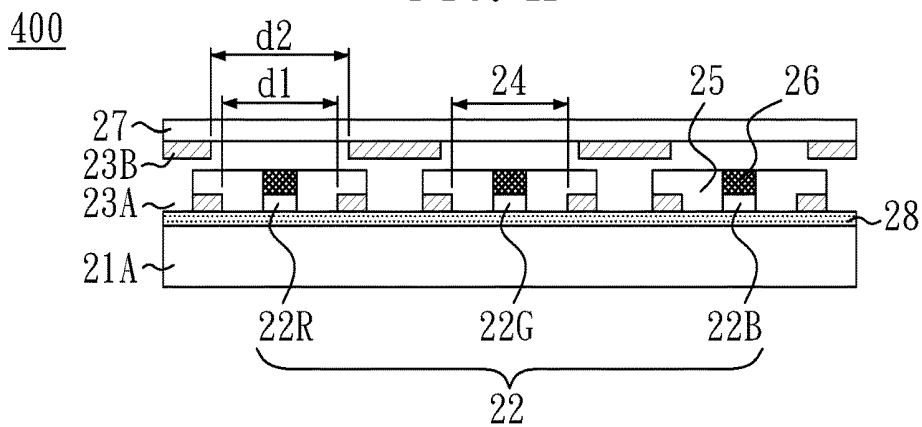


FIG. 4C

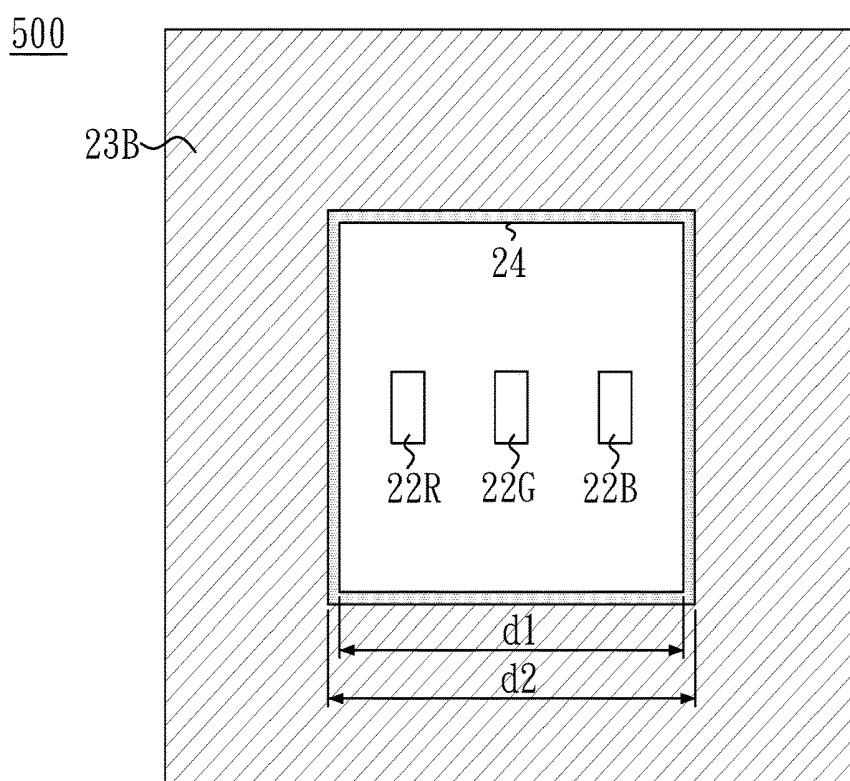


FIG. 5A

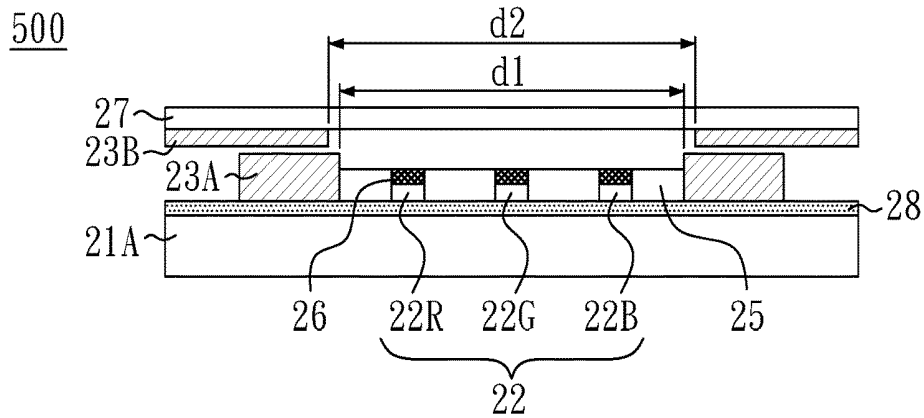


FIG. 5B

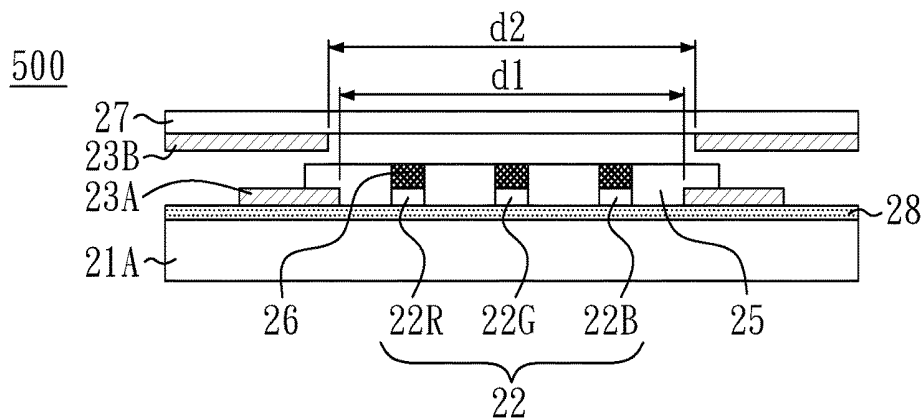


FIG. 5C

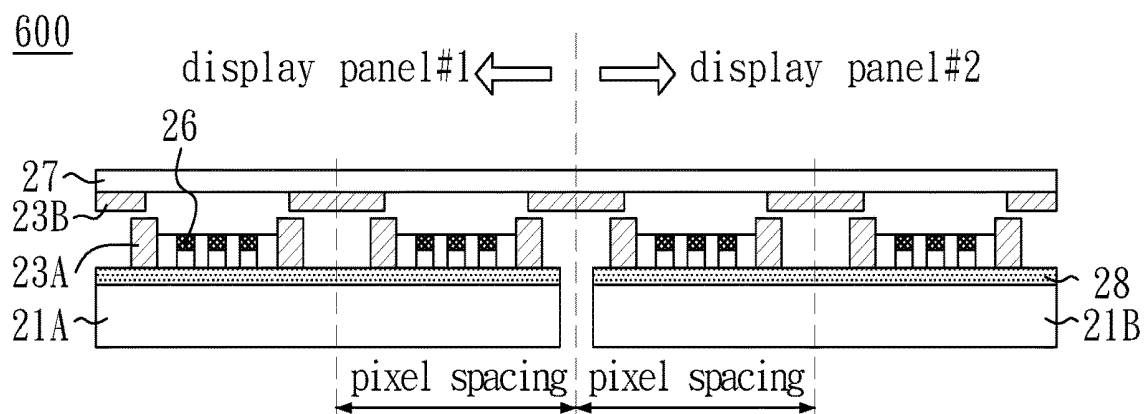


FIG. 6

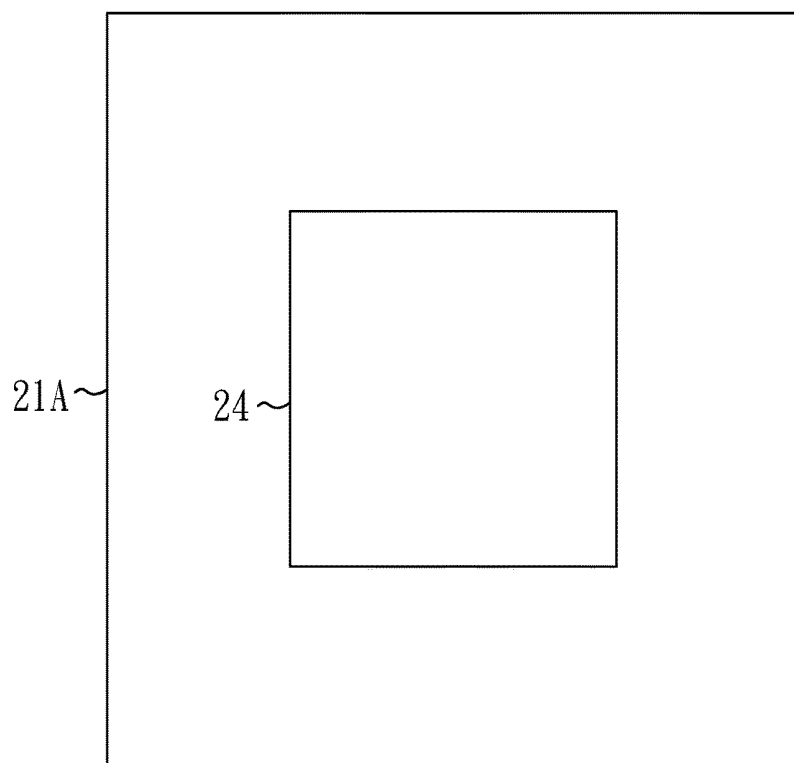


FIG. 7A



FIG. 7B

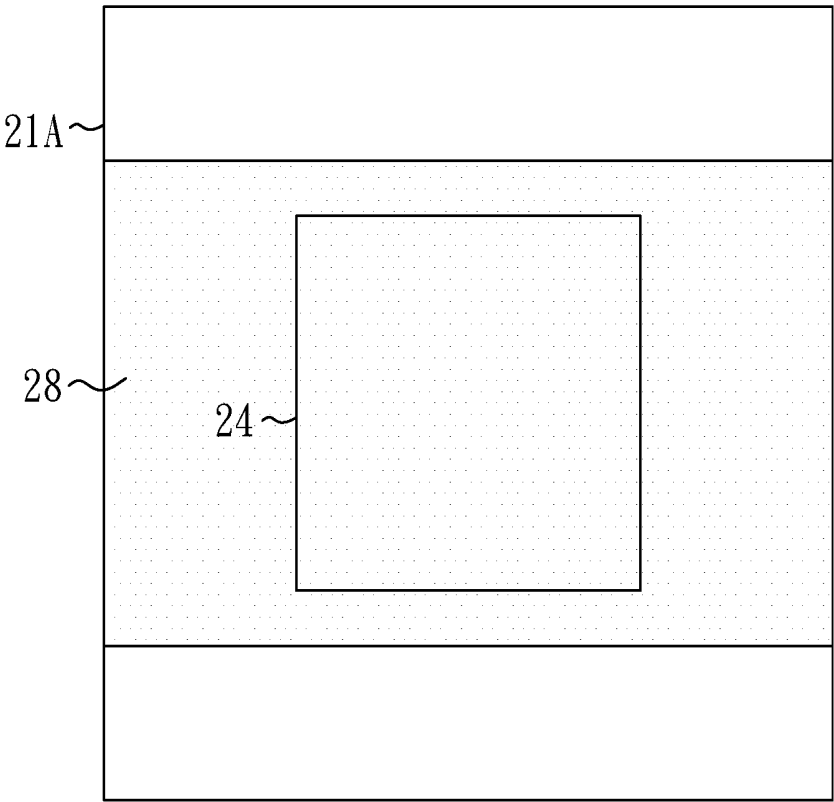


FIG. 8A

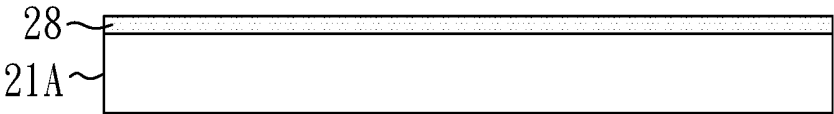


FIG. 8B

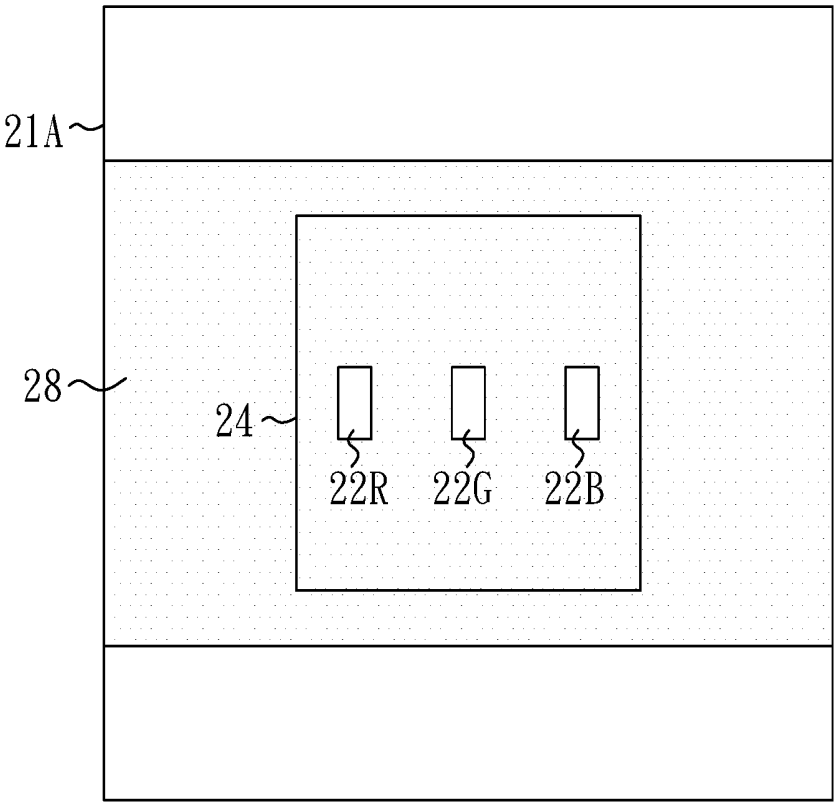


FIG. 9A

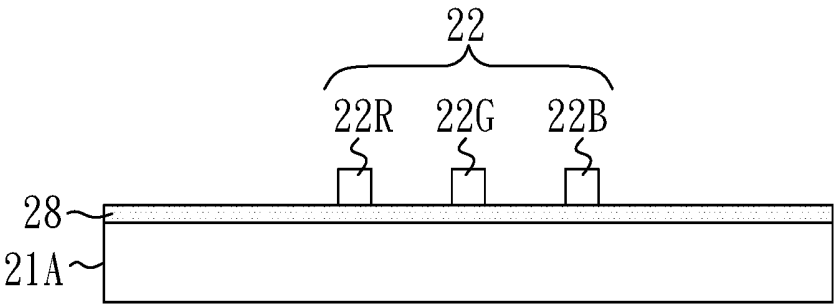


FIG. 9B

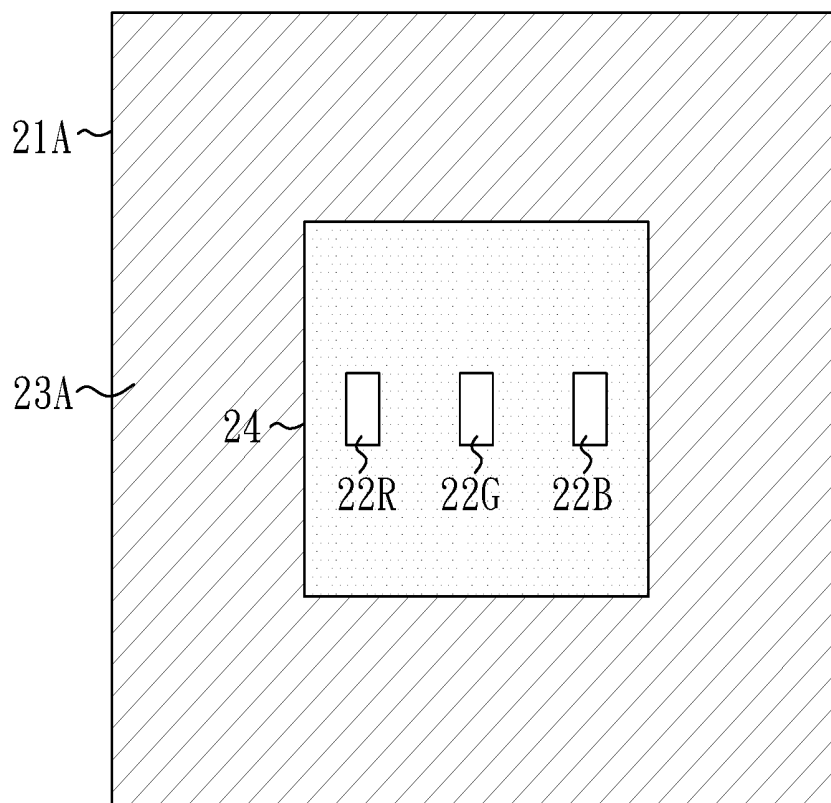


FIG. 10A

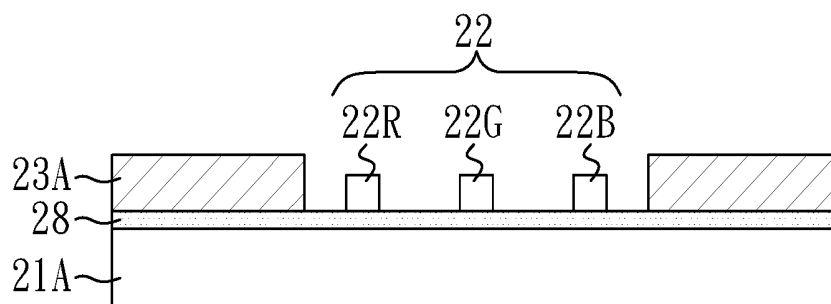


FIG. 10B

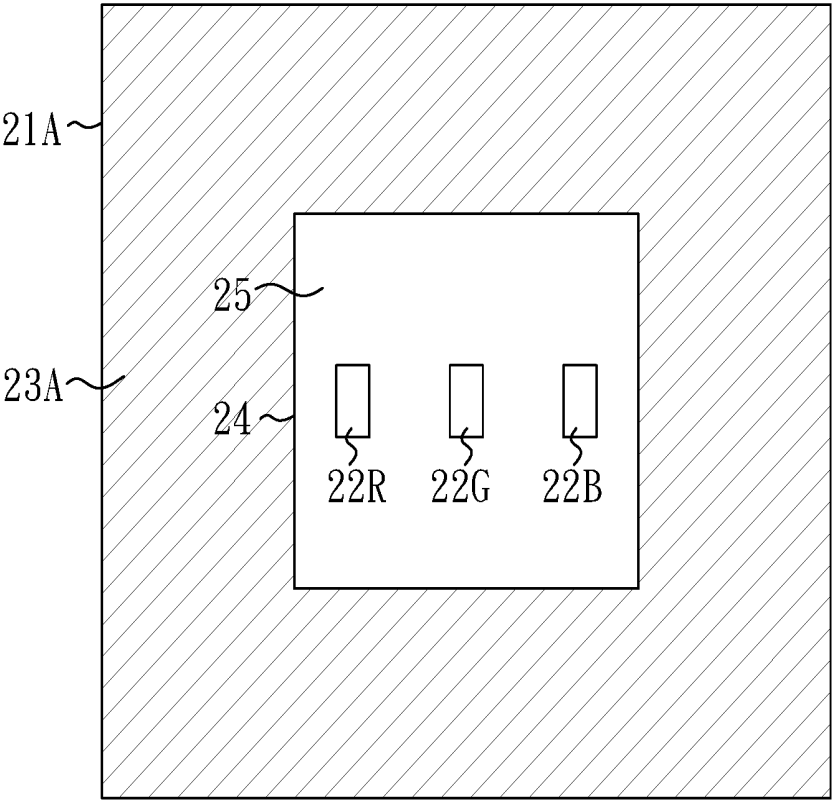


FIG. 11A

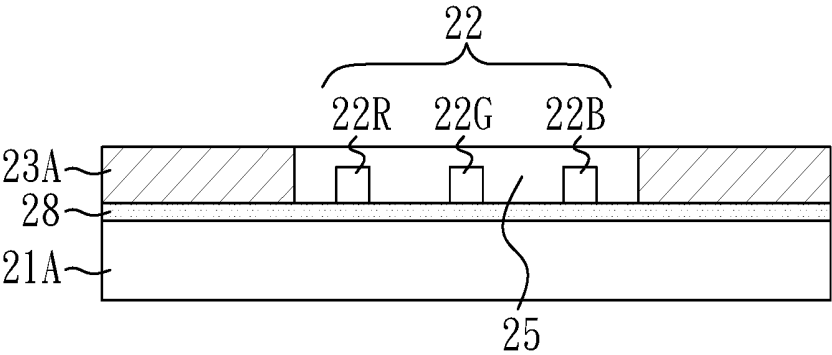


FIG. 11B

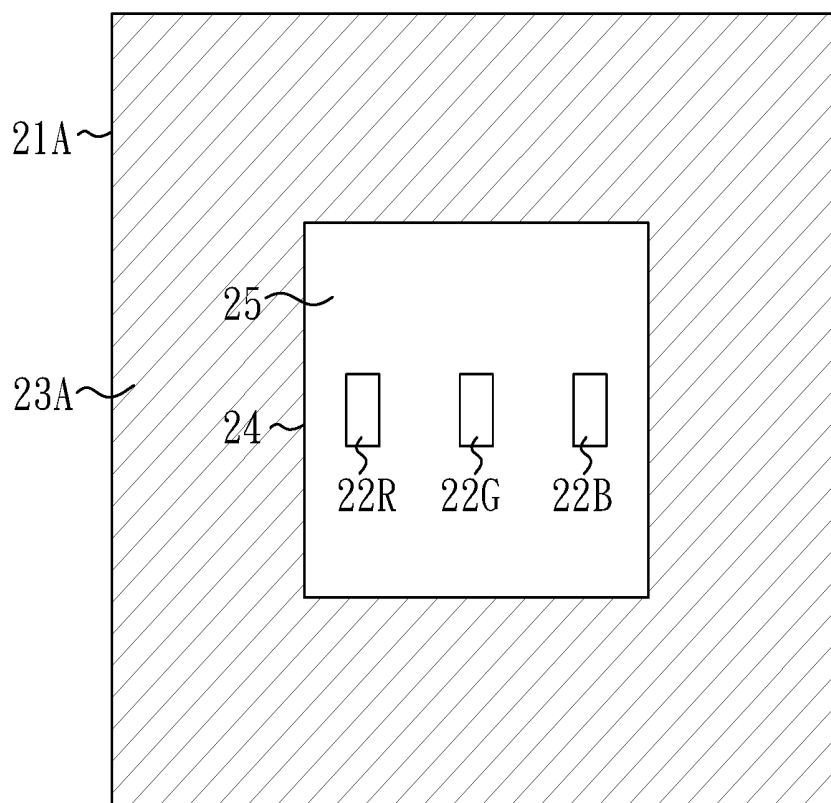


FIG. 12A

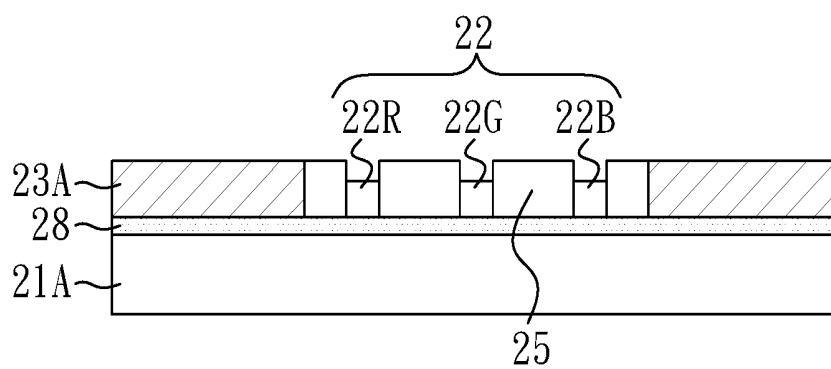


FIG. 12B

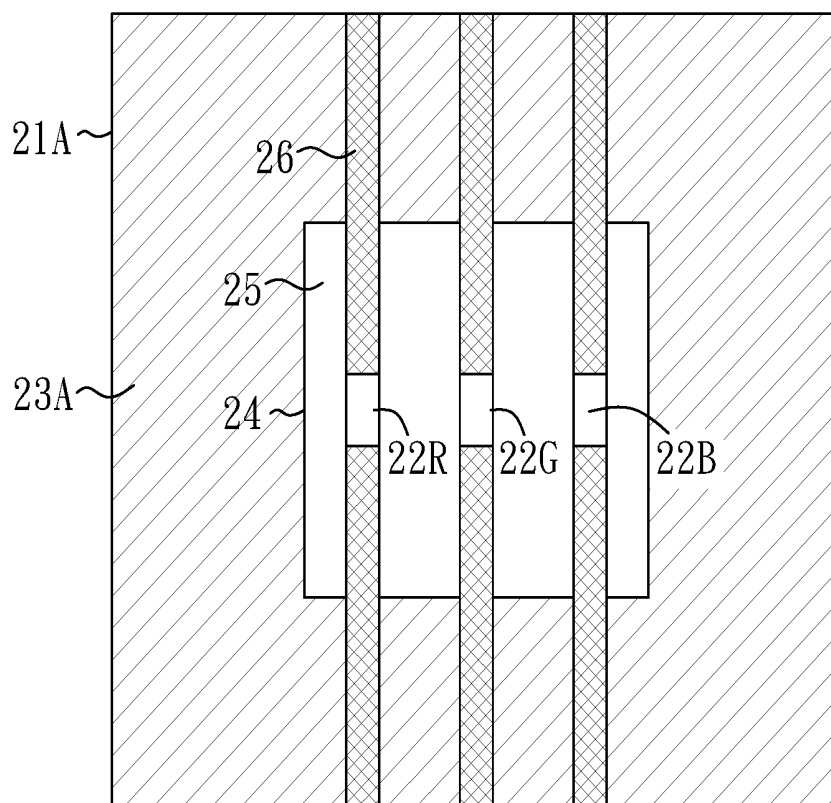


FIG. 13A

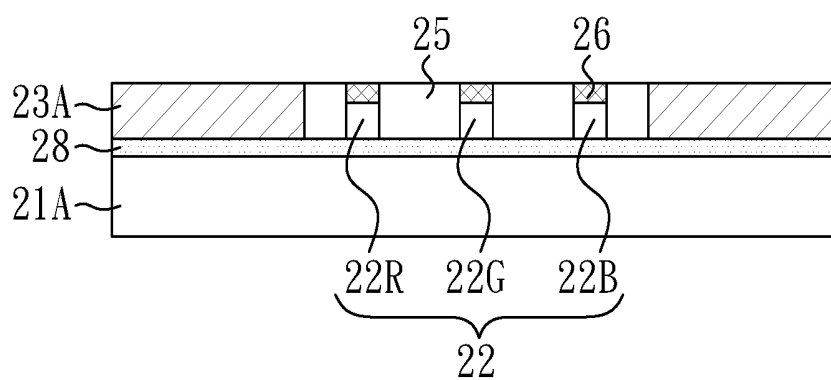


FIG. 13B

1400

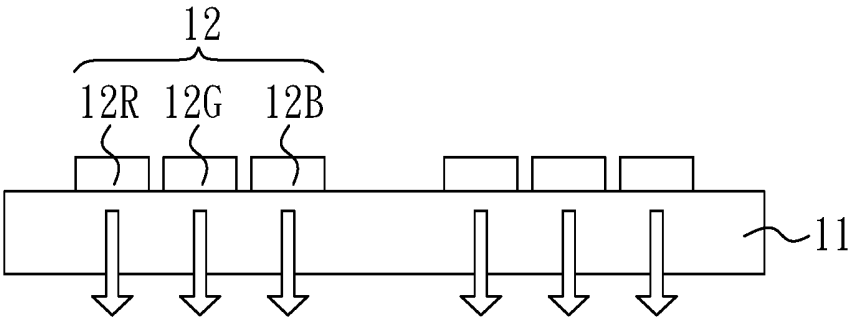


FIG. 14

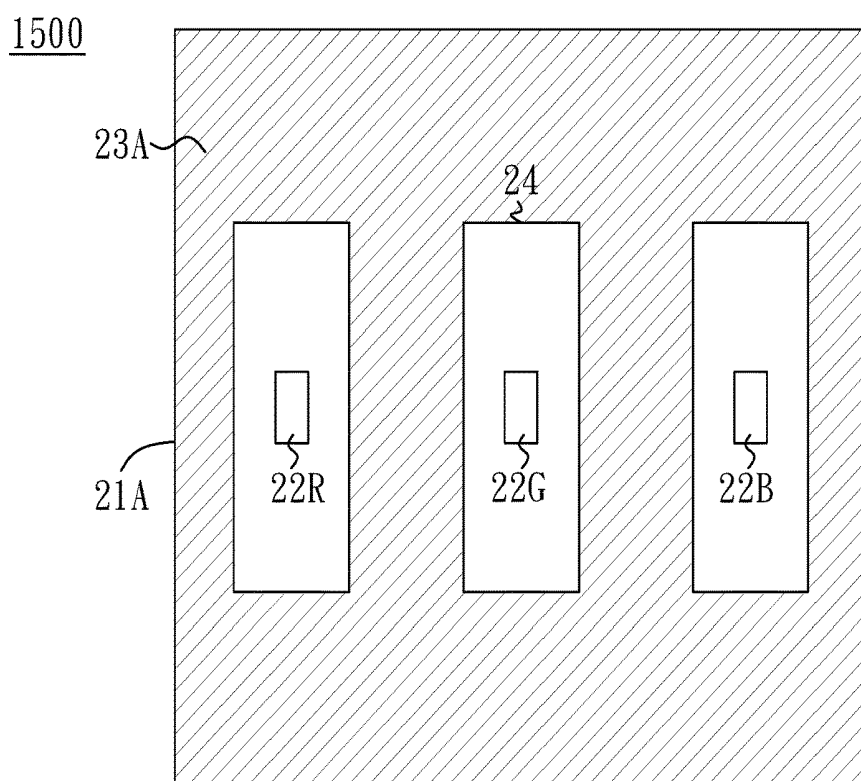


FIG. 15A

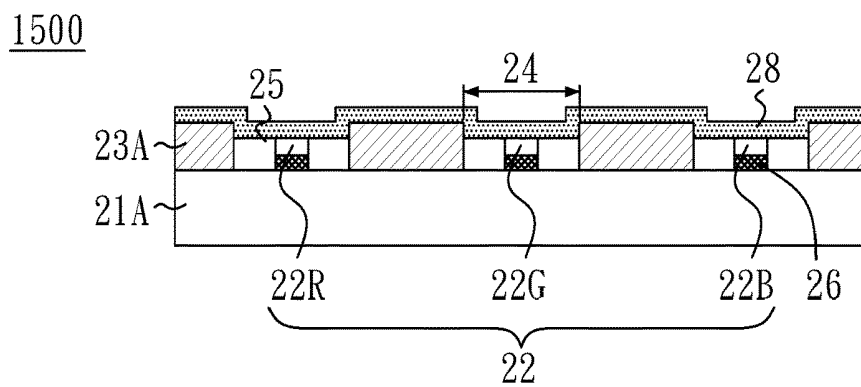


FIG. 15B

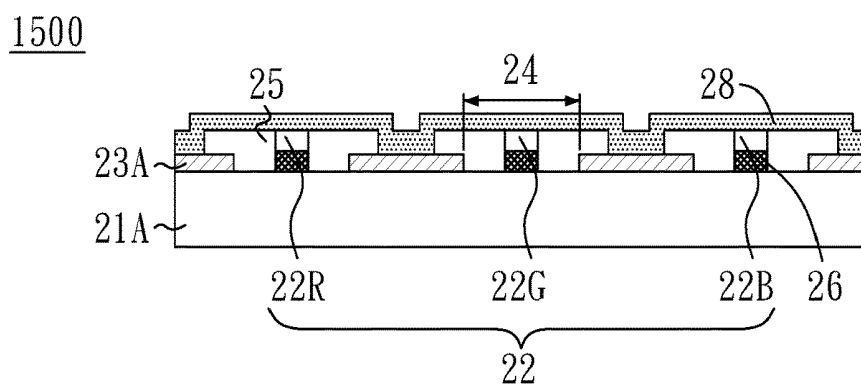


FIG. 15C

1500

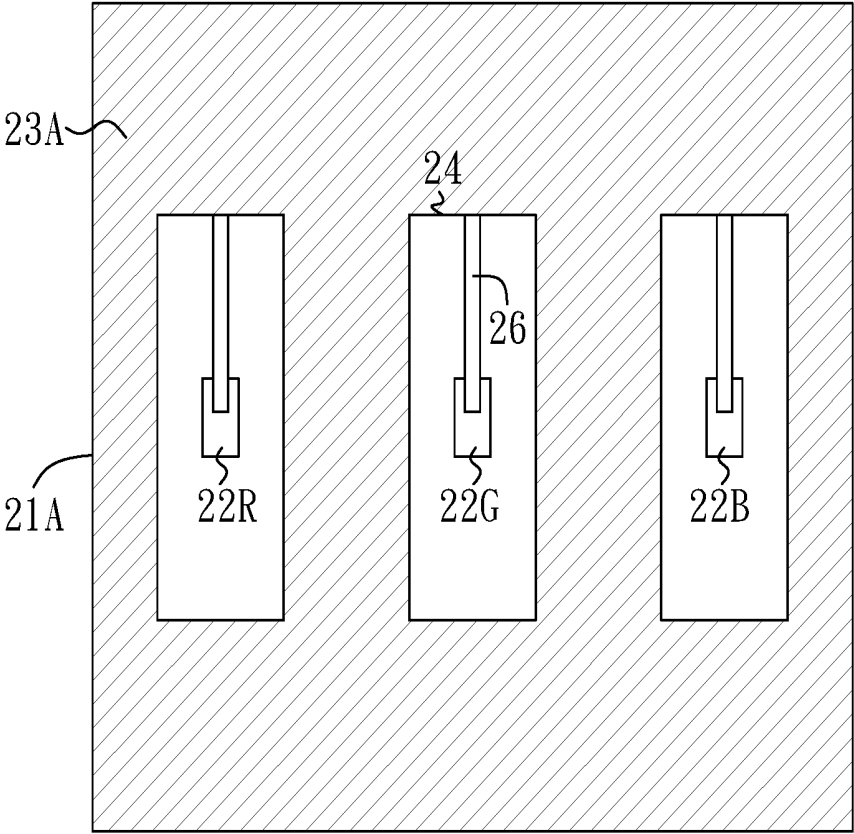


FIG. 15D

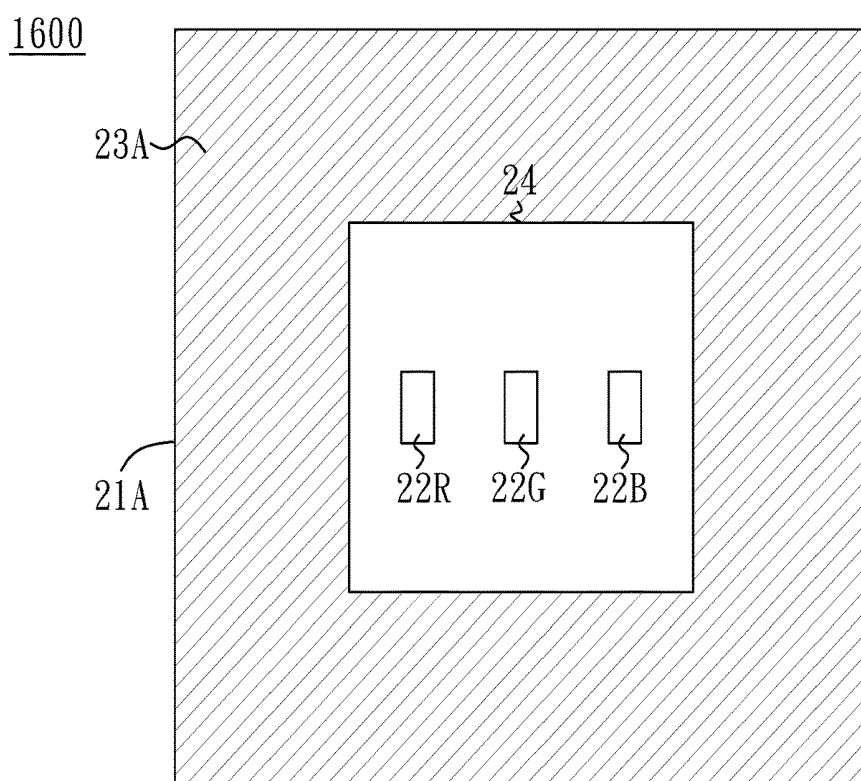


FIG. 16A

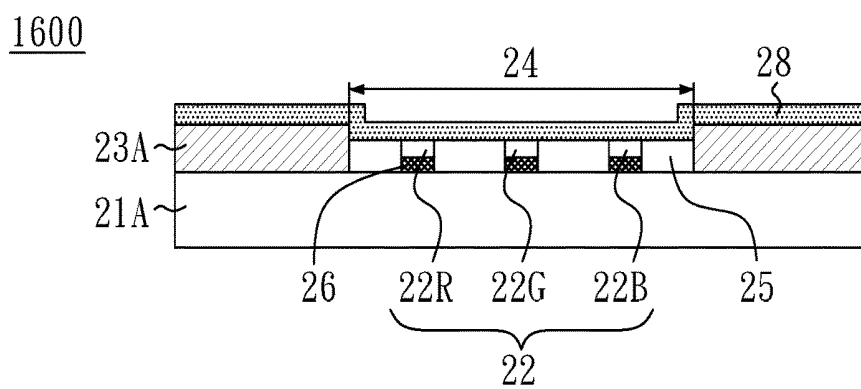


FIG. 16B

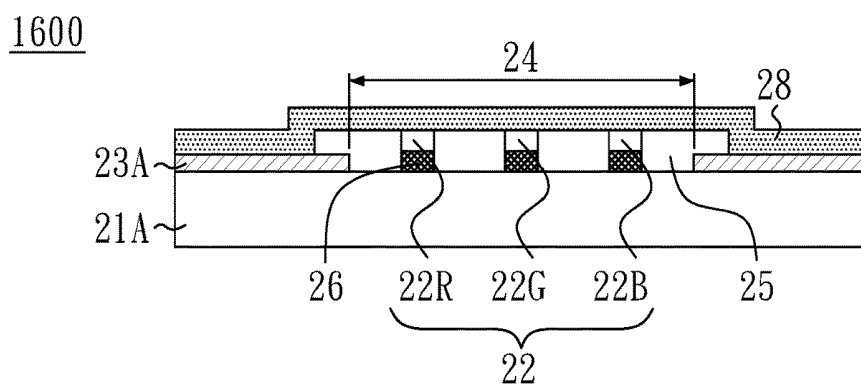


FIG. 16C

1600

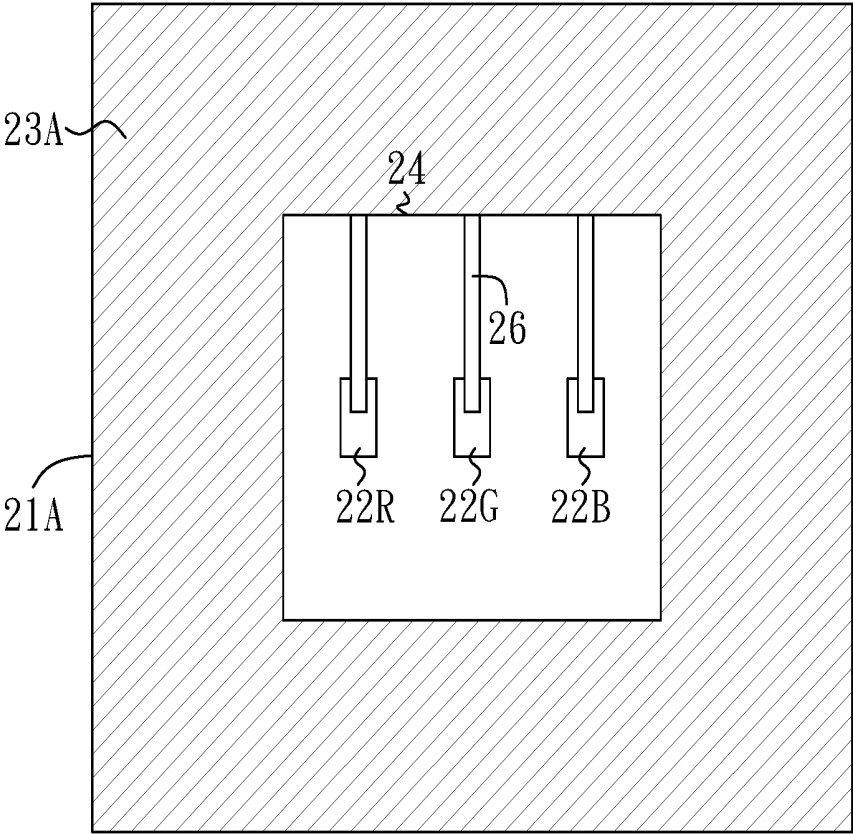


FIG. 16D

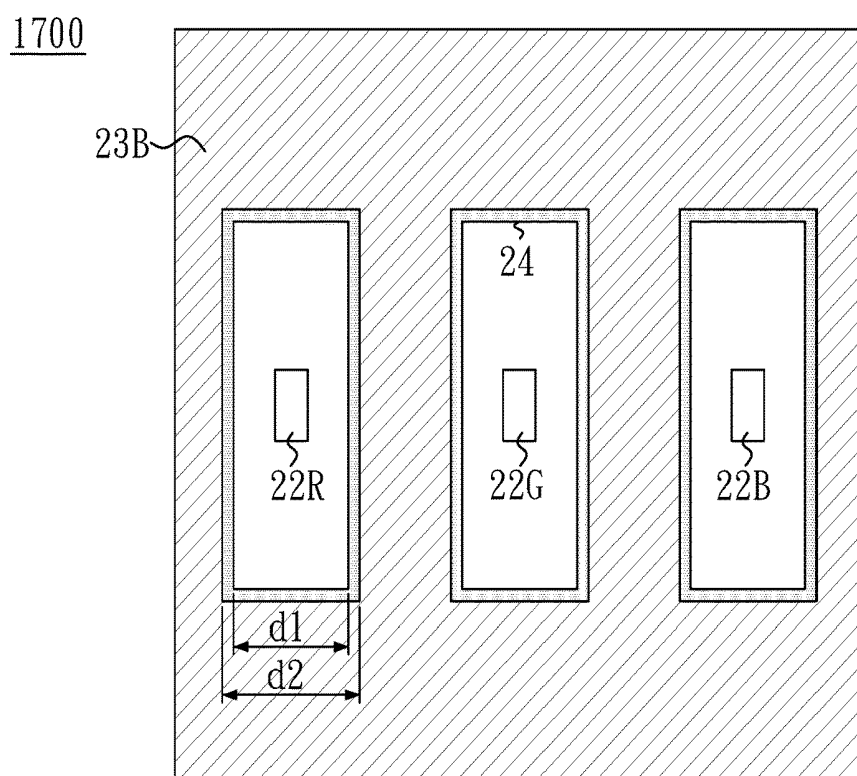


FIG. 17A

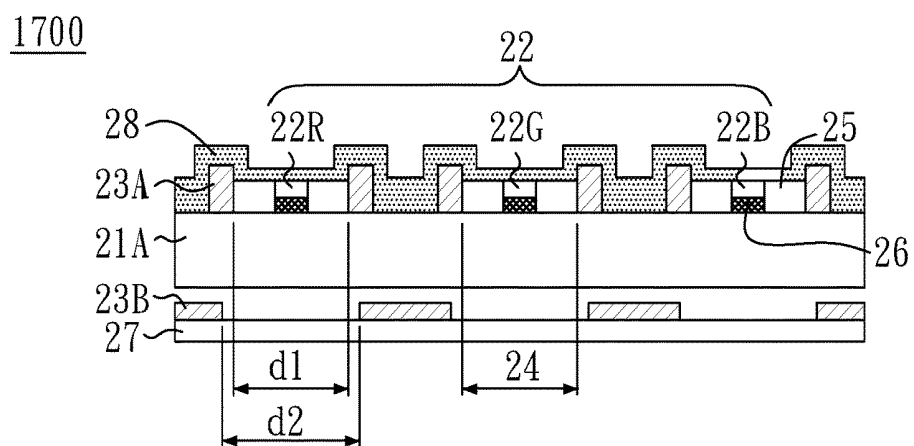


FIG. 17B

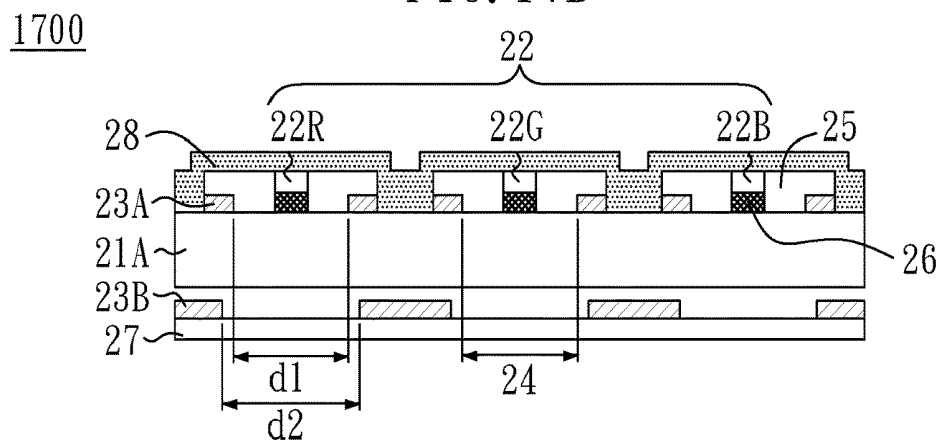


FIG. 17C

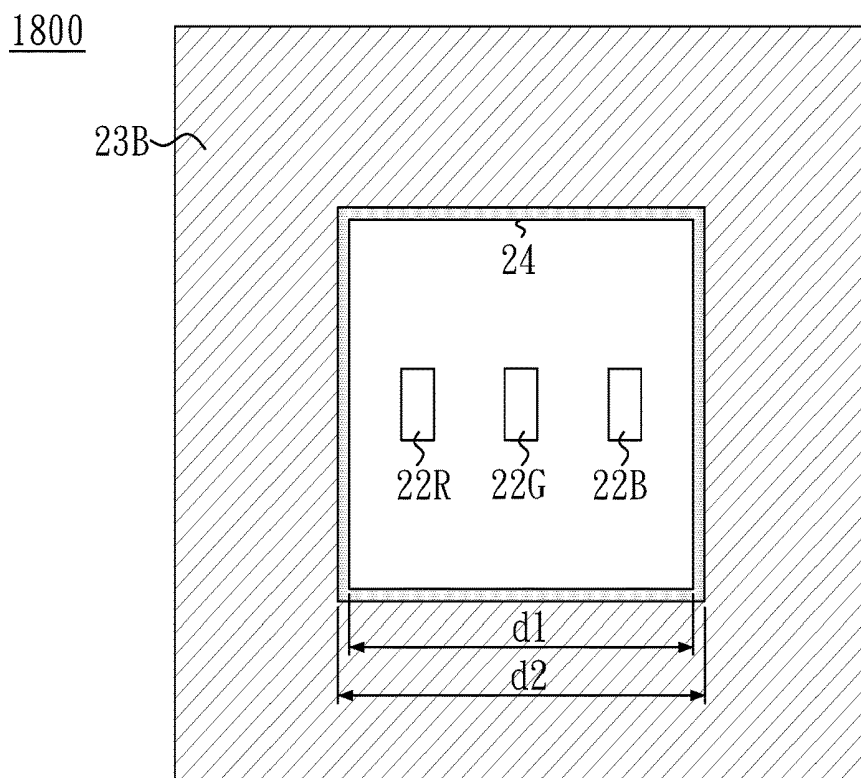


FIG. 18A

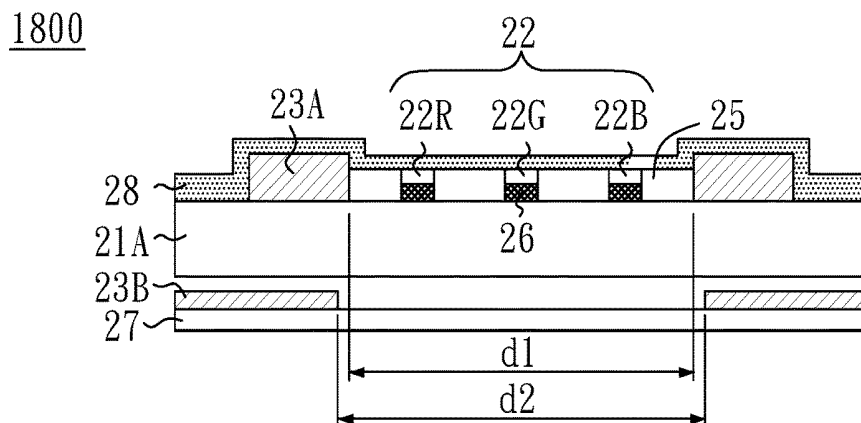


FIG. 18B

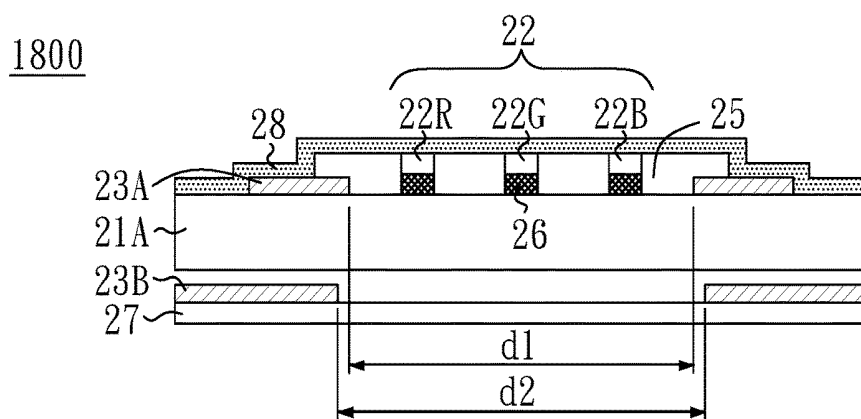


FIG. 18C

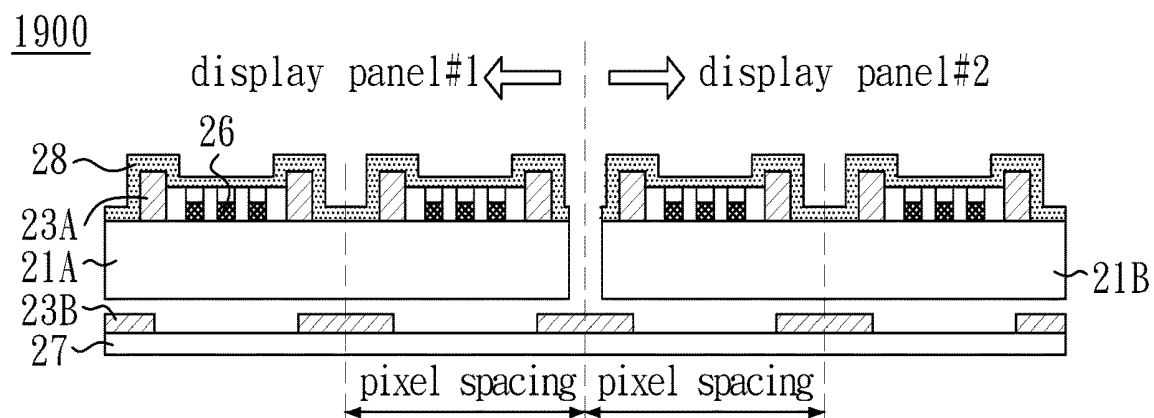


FIG. 19

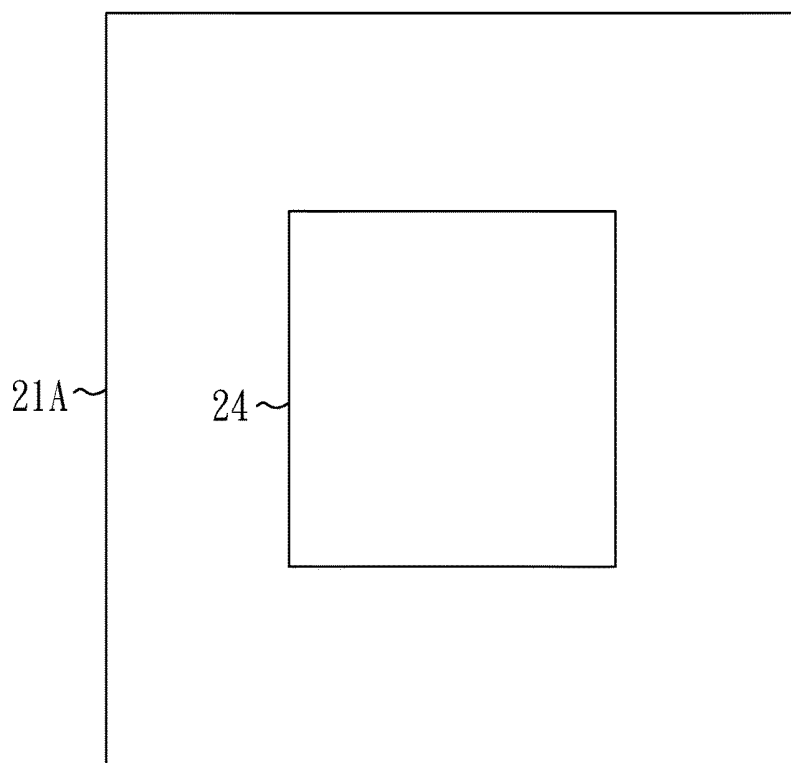


FIG. 20A



FIG. 20B

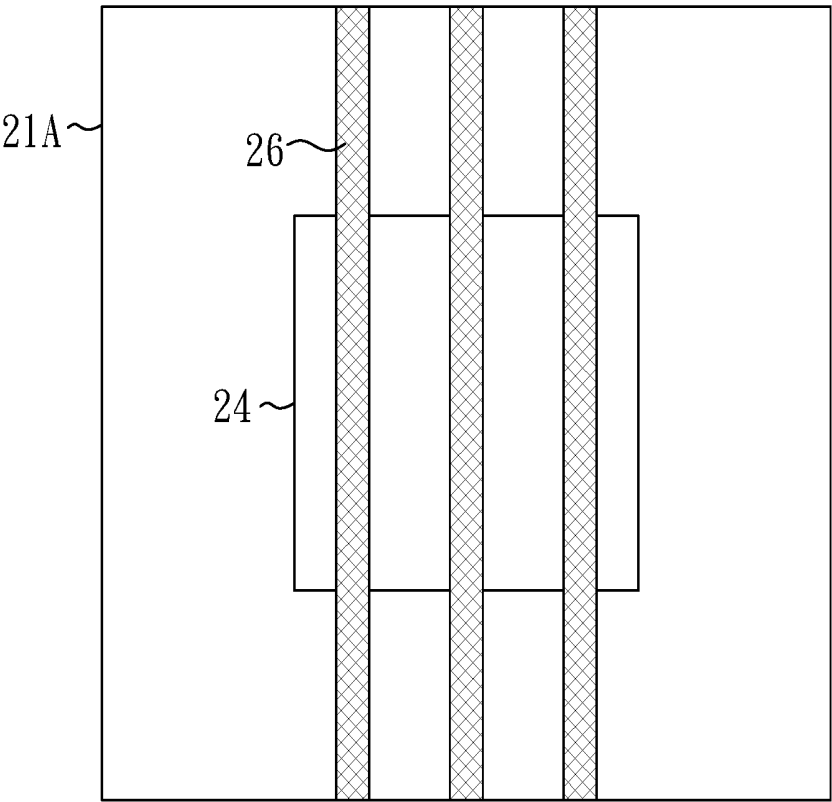


FIG. 21A

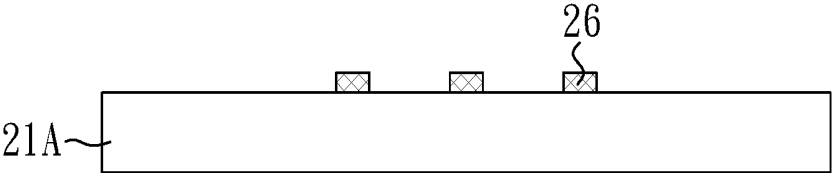


FIG. 21B

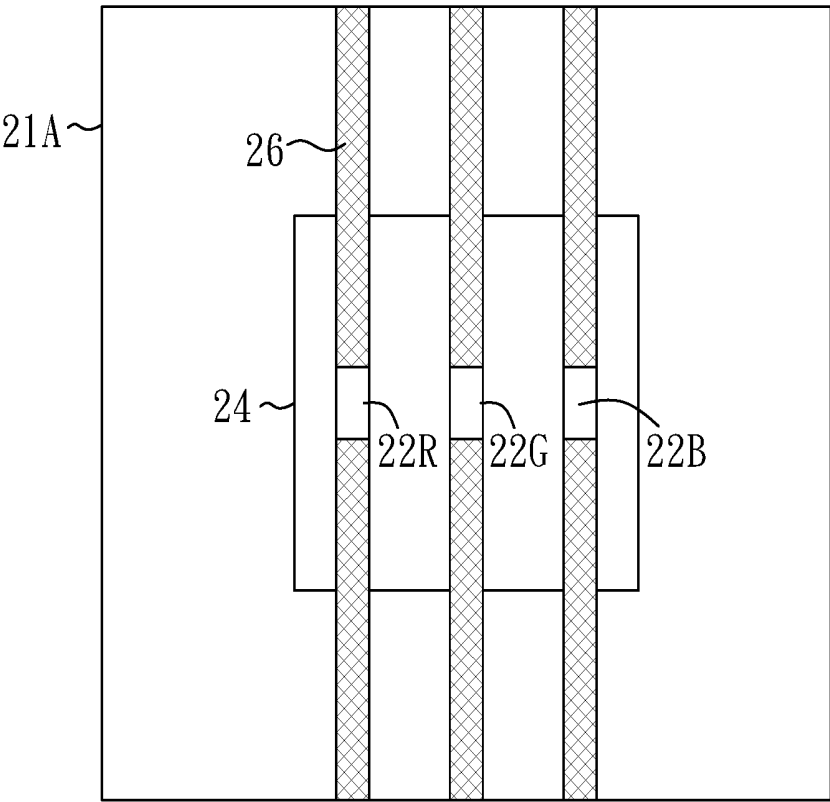


FIG. 22A

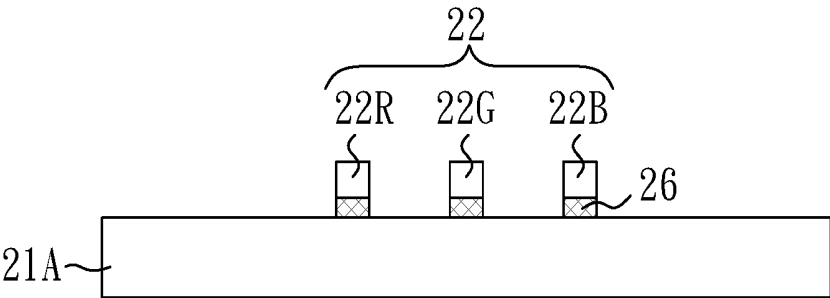


FIG. 22B

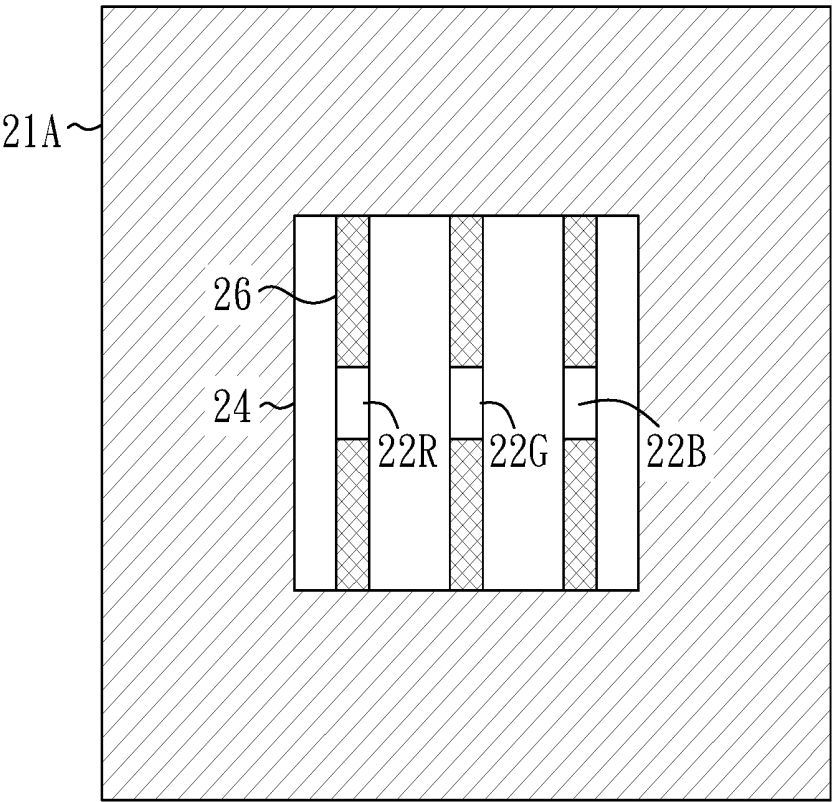


FIG. 23A

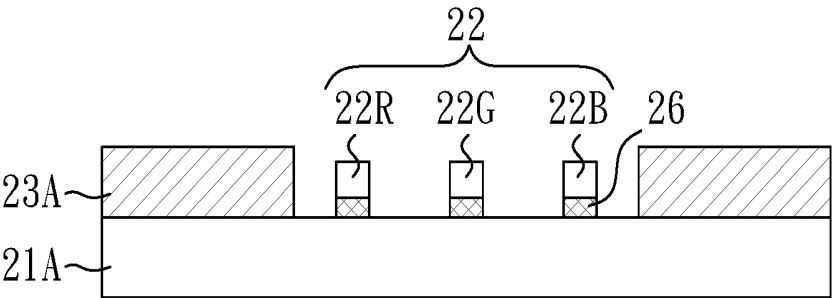


FIG. 23B

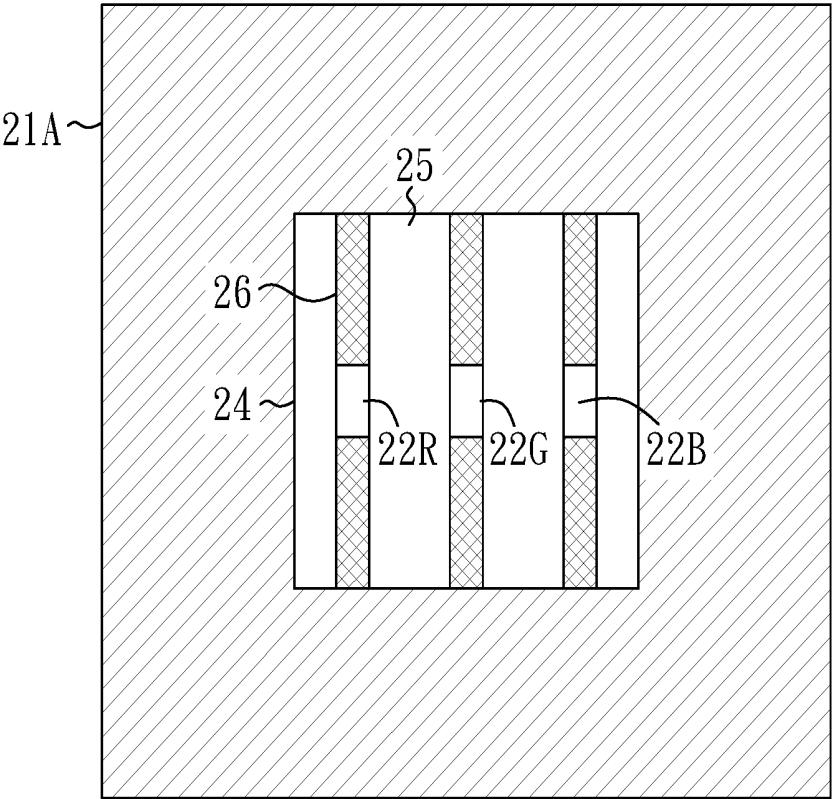


FIG. 24A

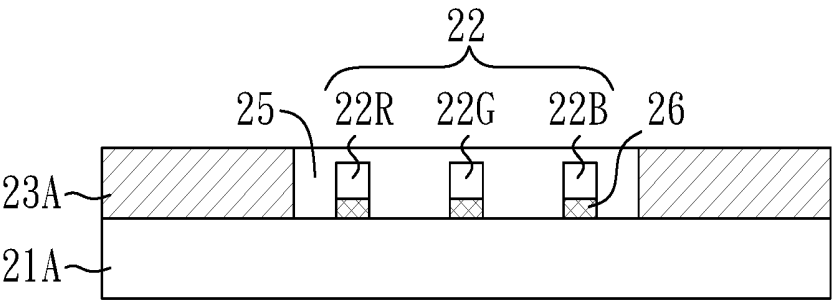


FIG. 24B

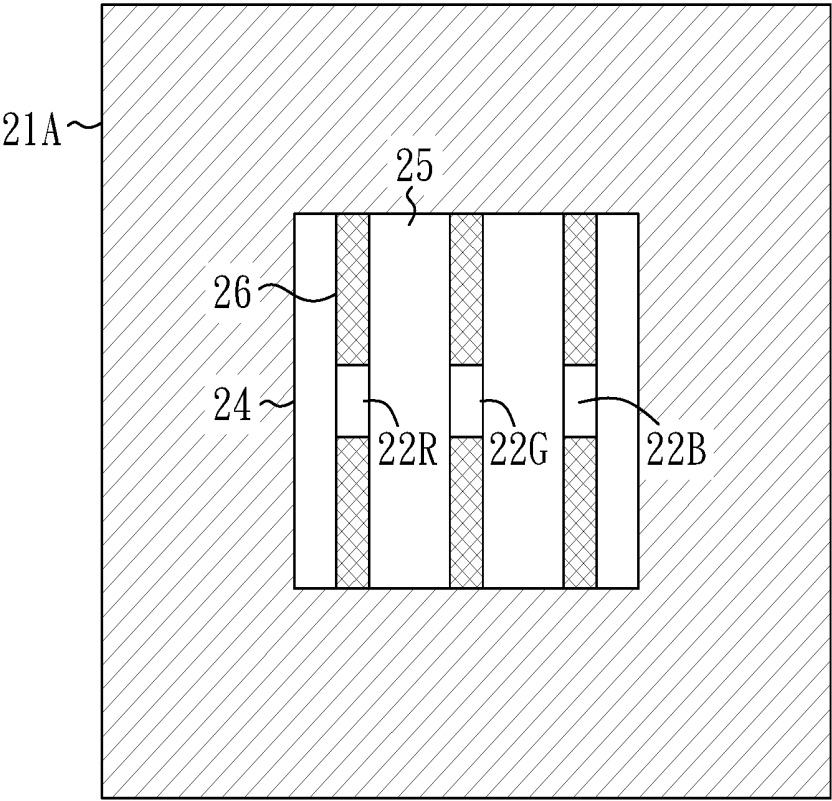


FIG. 25A

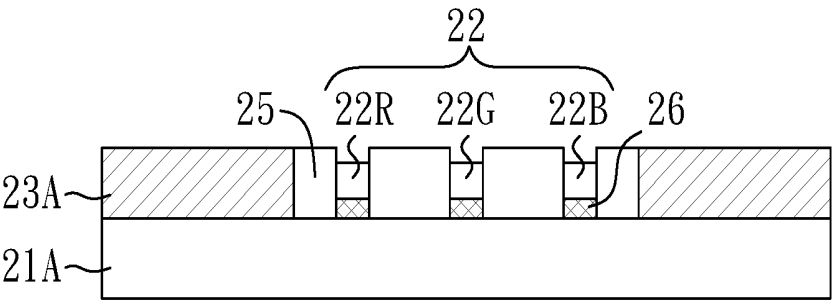


FIG. 25B

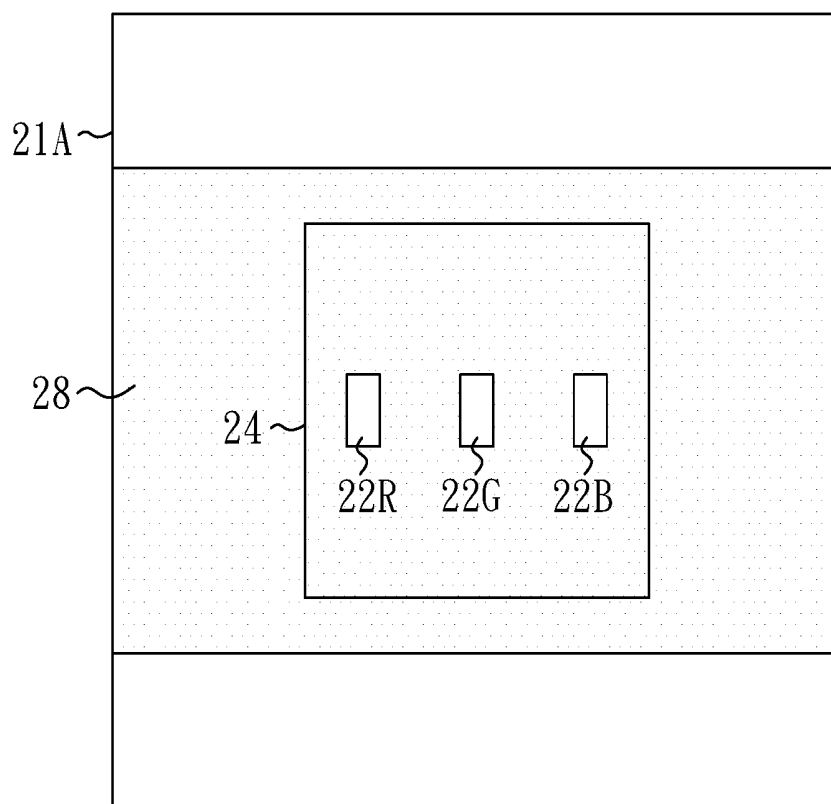


FIG. 26A

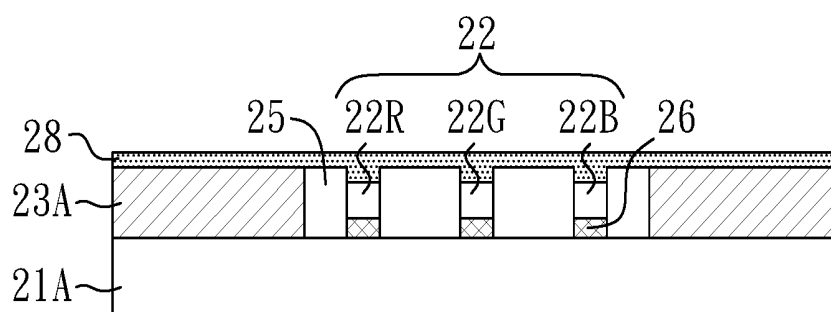


FIG. 26B

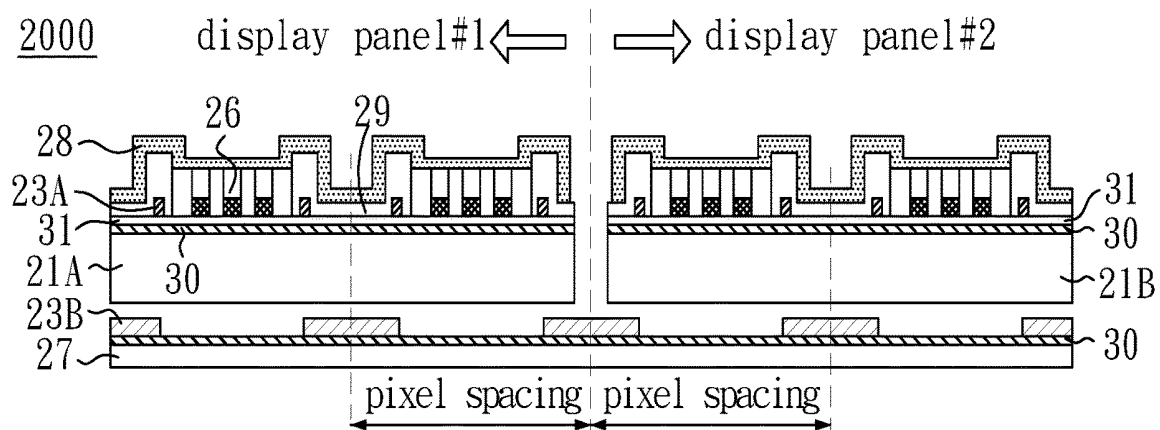


FIG. 27

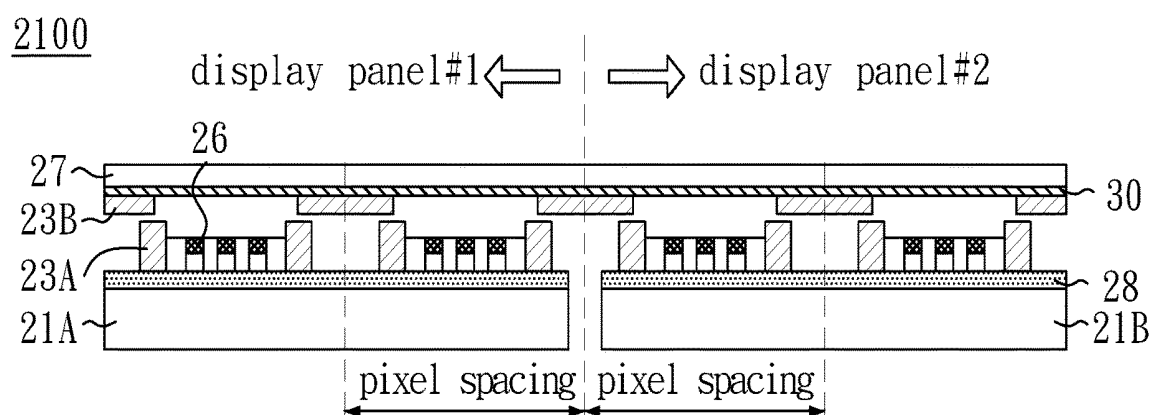


FIG. 28

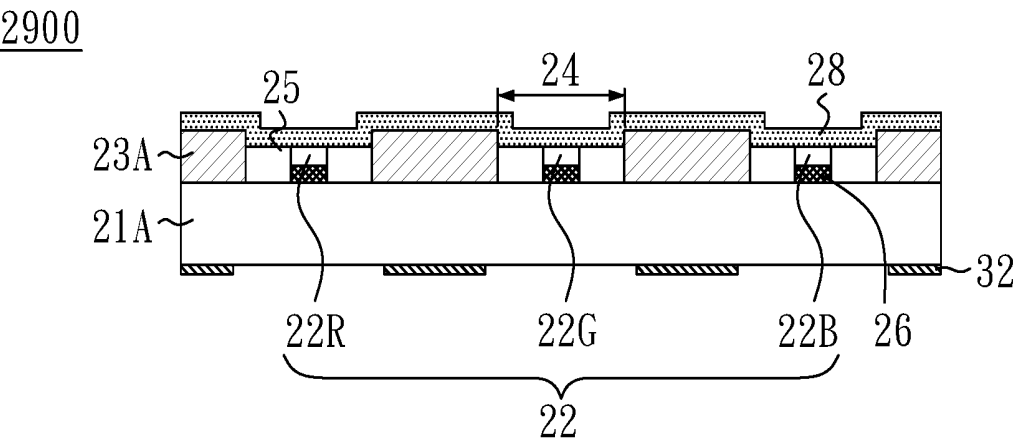


FIG. 29

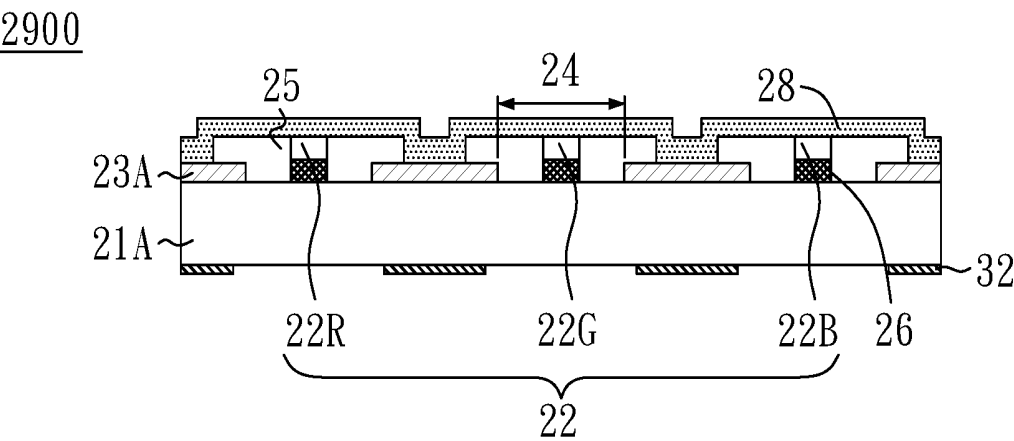


FIG. 30

3100

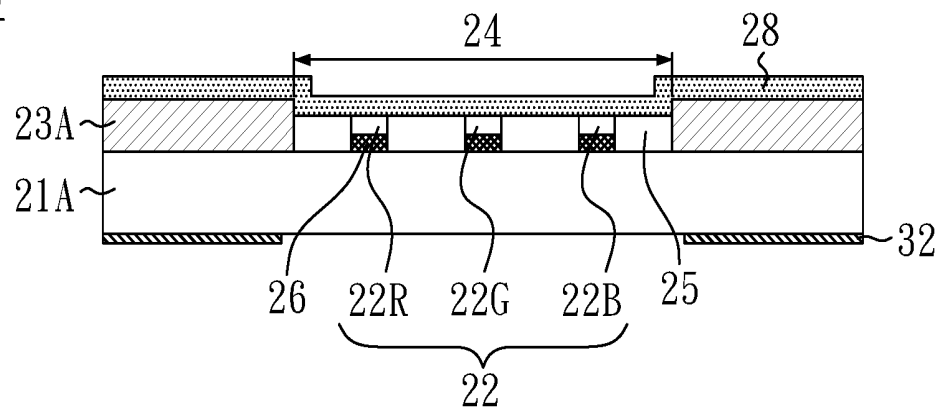


FIG. 31

3100

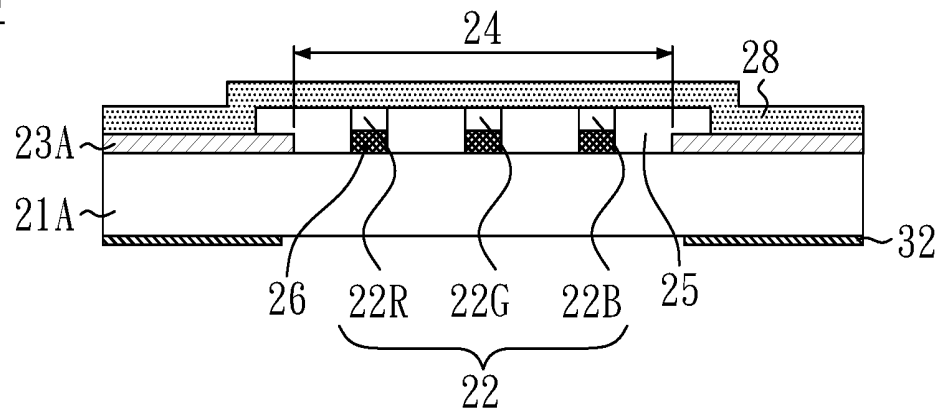


FIG. 32

TOP EMISSION MICROLED DISPLAY AND BOTTOM EMISSION MICROLED DISPLAY AND A METHOD OF FORMING THE SAME

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application is a continuation application of U.S. application Ser. No. 16/128,255, filed on Sep. 11, 2018, the entire contents of which are herein expressly incorporated by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0002] The present invention generally relates to a light-emitting diode (LED) display, and more particularly to a top emission microLED display and a bottom emission microLED display.

2. Description of Related Art

[0003] A micro light-emitting diode (microLED, mLED or μ LED) display panel is one type of flat display panel, which is composed of microscopic microLEDs each having a size of 1-10 micrometers.

[0004] Compared to conventional liquid crystal display panels, the microLED display panels offer better contrast, response time and energy efficiency. Although both organic light-emitting diodes (OLEDs) and microLEDs possess good energy efficiency, the microLEDs, based on group III/V (e.g., GaN) LED technology, offer higher brightness, higher luminous efficacy and longer lifespan than the OLEDs.

[0005] Active matrix using thin-film transistors (TFT) may be used in companion with microLEDs to drive a display panel. However, microLED is made by flip chip technology, while TFT is made by complementary metal-oxide-semiconductor (CMOS) process which is more complex than flip chip technology. These two distinct technologies may cause thermal mismatch. A drive current of the microLED is small in gray display, which may be significantly affected by leakage current.

[0006] Passive matrix is another driving method performed by a row drive circuit and a column drive circuit, which are disposed on the periphery of a display panel. When the size or the resolution of the display panel increases, output loading and delay of the drive circuits increase accordingly, causing the display panel to malfunction. Therefore, passive matrix is not suitable for large-size microLED display panels.

[0007] A need has thus arisen to propose a novel microLED display panel, particularly a large-size or high-resolution display panel, which is capable of maintaining advantages of microLEDs and overcoming disadvantages of driving schemes.

[0008] As adjacent microLEDs are near to each other, interference (e.g., color mixing) between adjacent microLEDs may happen and thus decrease contrast ratio. Moreover, non-uniform display may happen due to connecting wires composed of opaque or reflective material that connecting the microLEDs with other components or circuits.

[0009] A need has thus arisen to propose a novel microLED display with luminous efficacy improvement over the conventional microLED displays.

SUMMARY OF THE INVENTION

[0010] In view of the foregoing, it is an object of the embodiment of the present invention to provide structures and forming methods of a top emission microLED display and a bottom emission microLED display capable of preventing interference, color mixing and non-uniform display issues.

[0011] According to one embodiment, a top emission microLED display includes a first main substrate; a bottom common electrode layer disposed on a top surface of the first main substrate; a plurality of microLEDs disposed on the bottom common electrode layer; a first light blocking layer disposed on the bottom common electrode layer to define a plurality of emission areas; a light guiding layer disposed in the emission areas; and a plurality of connecting structures disposed in the emission areas respectively and electrically connected with the microLEDs.

[0012] According to another embodiment, a bottom emission microLED display includes a first main substrate; a plurality of microLEDs disposed above the first main substrate; a first light blocking layer disposed above the first main substrate to define a plurality of emission areas; a light guiding layer disposed in the emission areas; a plurality of connecting structures disposed in the emission areas respectively and electrically connected with the microLEDs; and a top common electrode layer disposed above the first light blocking layer and the microLEDs.

BRIEF DESCRIPTION OF THE DRAWINGS

[0013] FIG. 1 schematically shows a side view of a top emission microLED display;

[0014] FIG. 2A shows a top view of a top emission microLED display according to a first embodiment of the present invention;

[0015] FIG. 2B shows a cross-sectional view of FIG. 2A;

[0016] FIG. 2C shows a cross-sectional view of a top emission microLED display according to a modified first embodiment of the present invention;

[0017] FIG. 2D shows another top view of the top emission microLED display according to the first embodiment of the present invention;

[0018] FIG. 3A shows a top view of a top emission microLED display according to a second embodiment of the present invention;

[0019] FIG. 3B shows a cross-sectional view of FIG. 3A;

[0020] FIG. 3C shows a cross-sectional view of a top emission microLED display according to a modified second embodiment of the present invention;

[0021] FIG. 3D shows another top view of the top emission microLED display according to the second embodiment of the present invention;

[0022] FIG. 4A shows a top view of a top emission microLED display according to a third embodiment of the present invention;

[0023] FIG. 4B shows a cross-sectional view of FIG. 4A;

[0024] FIG. 4C shows a cross-sectional view of a top emission microLED display according to a modified third embodiment of the present invention;

[0025] FIG. 5A shows a top view of a top emission microLED display according to a fourth embodiment of the present invention;

[0026] FIG. 5B shows a cross-sectional view of FIG. 5A;

[0027] FIG. 5C shows a cross-sectional view of a top emission microLED display according to a modified fourth embodiment of the present invention;

[0028] FIG. 6 shows a cross-sectional view of a top emission microLED display according to a fifth embodiment of the present invention;

[0029] FIG. 7A to FIG. 13B show top views and cross-sectional views illustrating steps of forming a top emission microLED display according to one embodiment of the present invention;

[0030] FIG. 14 schematically shows a side view of a bottom emission micro light-emitting diode (microLED) display;

[0031] FIG. 15A shows a top view of a bottom emission microLED display according to a sixth embodiment of the present invention;

[0032] FIG. 15B shows a cross-sectional view of FIG. 15A;

[0033] FIG. 15C shows a cross-sectional view of a bottom emission microLED display according to a modified sixth embodiment of the present invention;

[0034] FIG. 15D shows another top view of the bottom emission microLED display according to the sixth embodiment of the present invention;

[0035] FIG. 16A shows a top view of a bottom emission microLED display according to a seventh embodiment of the present invention;

[0036] FIG. 16B shows a cross-sectional view of FIG. 16A;

[0037] FIG. 16C shows a cross-sectional view of a bottom emission microLED display according to a modified seventh embodiment of the present invention;

[0038] FIG. 16D shows another top view of the bottom emission microLED display according to the seventh embodiment of the present invention;

[0039] FIG. 17A shows a top view of a bottom emission microLED display according to an eighth embodiment of the present invention;

[0040] FIG. 17B shows a cross-sectional view of FIG. 17A;

[0041] FIG. 17C shows a cross-sectional view of a bottom emission microLED display according to a modified eighth embodiment of the present invention;

[0042] FIG. 18A shows a top view of a bottom emission microLED display according to a ninth embodiment of the present invention;

[0043] FIG. 18B shows a cross-sectional view of FIG. 18A;

[0044] FIG. 18C shows a cross-sectional view of a bottom emission microLED display according to a modified ninth embodiment of the present invention;

[0045] FIG. 19 shows a cross-sectional view of a bottom emission microLED display according to a tenth embodiment of the present invention;

[0046] FIG. 20A to FIG. 26B show top views and cross-sectional views illustrating steps of forming a bottom emission microLED display according to one embodiment of the present invention;

[0047] FIG. 27 shows a cross-sectional view of a bottom emission microLED display according to an eleventh embodiment of the present invention;

[0048] FIG. 28 shows a cross-sectional view of a top emission microLED display according to a twelfth embodiment of the present invention;

[0049] FIG. 29 shows a cross-sectional view of a bottom emission microLED display according to a thirteenth embodiment of the present invention;

[0050] FIG. 30 shows a cross-sectional view of a bottom emission microLED display according to a modified thirteenth embodiment of the present invention;

[0051] FIG. 31 shows a cross-sectional view of a bottom emission microLED display according to a fourteenth embodiment of the present invention; and

[0052] FIG. 32 shows a cross-sectional view of a bottom emission microLED display according to a modified fourteenth embodiment of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

[0053] FIG. 1 schematically shows a side view of a top emission micro light-emitting diode (microLED) display 100. In the embodiment, microLEDs 12 (e.g., red microLED 12R, green microLED 12G and blue microLED 12B) may be disposed on a top surface of a main substrate 11 by a bonding technique. As the microLEDs 12 emit light upward (as shown by arrows) against the top surface of the main substrate 11, the display 100 is called a top emission microLED display. In the specification, the microLEDs 12 have a size of 1-10 micrometers, which may be decreased or increased according to specific applications or technological development in the future.

[0054] FIG. 2A shows a top view of a top emission microLED display 200 according to a first embodiment of the present invention, and FIG. 2B shows a cross-sectional view of FIG. 2A. In the embodiment, microLEDs 22 (e.g., red microLED 22R, green microLED 22G and blue microLED 22B) may be disposed above a (first) main substrate 21A. A (first) light blocking layer 23A is disposed between adjacent microLEDs 22 and above the (first) main substrate 21A to prevent interference (e.g., color mixing) between adjacent microLEDs 22 and to enhance contrast. A bottom common electrode layer 28 may be disposed between the main substrate 21A and the microLEDs 22. In the present embodiment (and the following embodiments), the microLED 22 may be a rectangle, for example, with a length of 25 micrometers and a width of 10 micrometers. According to one aspect of the embodiment, the microLEDs 22 may be disposed longitudinally. That is, the length of the microLED 22 is parallel to the longitude of the display 200, and the width of the microLED is parallel to the latitude of the display 200. As human eyes are more sensitive to vertically emitted light than horizontally emitted light, the display 200 of the embodiment can enhance viewing angle.

[0055] The (first) light blocking layer 23A of the embodiment may include black matrix (BM). In the embodiment shown in FIG. 2B, black resin is first formed, followed by adopting photo process and curing process to form the BM (first) light blocking layer 23A. In another embodiment, ink-jet printing technique and curing process are adopted to form the BM (first) light blocking layer 23A.

[0056] The (first) light blocking layer 23A defines emission areas 24, which are not covered with the (first) light

blocking layer 23A. In other words, areas other than the emission areas 24 are covered with the (first) light blocking layer 23A. A light guiding layer 25, composed of light guiding material, is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. The light guiding material is transparent with high refractive index. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0057] In the embodiment, the (first) light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than or equal to the microLEDs 22.

[0058] FIG. 2C shows a cross-sectional view of a top emission microLED display 200 according to a modified first embodiment of the present invention. In the embodiment shown in FIG. 2C, the (first) light blocking layer 23A has a thickness less than the light guiding layer 25. Moreover, the (first) light blocking layer 23A and the light guiding layer 25 partially overlap each other, and the (first) light blocking layer 23A is partially covered with the light guiding layer 25. In the embodiment shown in FIG. 2C, a chromium/chromium oxide film is first formed, followed by adopting photo etching technique to form the BM (first) light blocking layer 23A.

[0059] FIG. 2D shows another top view of the top emission microLED display 200 according to the first embodiment of the present invention. A connecting structure 26, such as conductive electrode, is disposed on a top surface of the microLED 22 in each emission area 24. The connecting structure 26 may include transparent material (e.g., indium tin oxide), opaque material (e.g., metal) or reflective material. According to one aspect of the embodiment, the connecting structures 26 in the emission areas 24 have the same pattern, which can prevent nonuniform display issue.

[0060] FIG. 3A shows a top view of a top emission microLED display 300 according to a second embodiment of the present invention, and FIG. 3B shows a cross-sectional view of FIG. 3A. The second embodiment is similar to the first embodiment with the exception that, in the second embodiment, the (first) light blocking layer 23A is disposed between adjacent pixels (instead of adjacent microLEDs 22) to prevent interference (e.g., color mixing) between adjacent pixels and to enhance contrast.

[0061] The (first) light blocking layer 23A defines emission areas 24, which are not covered with the (first) light blocking layer 23A. In other words, areas other than the emission areas 24 are covered with the (first) light blocking layer 23A. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0062] In the embodiment, the (first) light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 3B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22.

[0063] FIG. 3C shows a cross-sectional view of a top emission microLED display 300 according to a modified second embodiment of the present invention. In the embodiment shown in FIG. 3C, the (first) light blocking layer 23A has a thickness less than the light guiding layer 25. Moreover, the (first) light blocking layer 23A and the light guiding layer 25 partially overlap each other, and the (first) light blocking layer 23A is partially covered with the light guiding layer 25.

[0064] FIG. 3D shows another top view of the top emission microLED display 300 according to the second embodiment of the present invention. A connecting structure 26, such as conductive electrode, is disposed on a top surface of the microLED 22 in each emission area 24. According to one aspect of the embodiment, the connecting structures 26 in the emission areas 24 have the same pattern and the connecting structures 26 in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0065] FIG. 4A shows a top view of a top emission microLED display 400 according to a third embodiment of the present invention, and FIG. 4B shows a cross-sectional view of FIG. 4A. In the embodiment, microLEDs 22 (e.g., red microLED 22R, green microLED 22G and blue microLED 22B) may be disposed above a (first) main substrate 21A. Each microLED 22 corresponds to an emission area 24. In the embodiment, a frame-shaped first light blocking layer 23A surrounds the emission area 24 and is disposed above the (first) main substrate 21A. In the embodiment, a blocking substrate 27 is disposed above the (first) main substrate 21A and the first light blocking layer 23A. A second light blocking layer 23B, which covers areas other than the emission areas 24 and the first light blocking layer 23A, is disposed on a bottom surface of the blocking substrate 27. The first light blocking layer 23A and the second light blocking layer 23B partially overlap each other. Accordingly, an aperture d1 of the first light blocking layer 23A is different from (e.g., smaller than) an aperture d2 of the second light blocking layer 23B. In another embodiment, the aperture of the first light blocking layer 23A is greater than the aperture of the second light blocking layer 23B. In the embodiment, the first light blocking layer 23A and the second light blocking layer 23B may include BM, and the blocking substrate 27 may include transparent material such as quartz, glass or plastic material.

[0066] A light guiding layer 25, composed of light guiding material, is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0067] In the embodiment, the first light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 4B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22.

[0068] FIG. 4C shows a cross-sectional view of a top emission microLED display 400 according to a modified third embodiment of the present invention. In the embodiment shown in FIG. 4C, the first light blocking layer 23A has a thickness less than the light guiding layer 25. Moreover, the first light blocking layer 23A is partially covered with the light guiding layer 25.

[0069] According to one aspect of the embodiment, the connecting structures 26 (not shown) in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0070] FIG. 5A shows a top view of a top emission microLED display 500 according to a fourth embodiment of the present invention, and FIG. 5B shows a cross-sectional view of FIG. 5A. The fourth embodiment is similar to the third embodiment with the exception that, in the fourth embodiment, the first light blocking layer 23A and the second light blocking layer 23B are disposed between

adjacent pixels (instead of adjacent microLEDs 22) to prevent interference (e.g., color mixing) between adjacent pixels and to enhance contrast.

[0071] In the embodiment, each pixel (which includes red microLED 22R, green microLED 22G and blue microLED 22B) corresponds to an emission area 24. In the embodiment, a frame-shaped first light blocking layer 23A surrounds the emission area 24 and is disposed above the (first) main substrate 21A. In the embodiment, a second light blocking layer 23B, which covers areas other than the emission areas 24 and the first light blocking layer 23A, is disposed on a bottom surface of the blocking substrate 27. The first light blocking layer 23A and the second light blocking layer 23B partially overlap each other. Accordingly, an aperture d1 of the first light blocking layer 23A is different from (e.g., smaller than) an aperture d2 of the second light blocking layer 23B. In the embodiment, the first light blocking layer 23A and the second light blocking layer 23B may include BM, and the blocking substrate 27 may include transparent material such as quartz, glass or plastic material.

[0072] A light guiding layer 25, composed of light guiding material, is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0073] In the embodiment, the first light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 5B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22.

[0074] FIG. 5C shows a cross-sectional view of a top emission microLED display 500 according to a modified fourth embodiment of the present invention. In the embodiment shown in FIG. 5C, the first light blocking layer 23A has a thickness less than the light guiding layer 25. Moreover, the first light blocking layer 23A is partially covered with the light guiding layer 25.

[0075] According to one aspect of the embodiment, the connecting structures 26 (not shown) in the emission areas 24 have the same pattern and the connecting structures 26 in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0076] FIG. 6 shows a cross-sectional view of a top emission microLED display 600 according to a fifth embodiment of the present invention. In the embodiment, the top emission microLED display 600 may include a first main substrate 21A and a second main substrate 21B, which are disposed at a same level but correspond to distinct microLED displays, respectively. A first light blocking layer 23A is disposed above the first main substrate 21A and the second main substrate 21B. Similar to the fourth embodiment, the top emission microLED display 600 may include a second light blocking layer 23B, which covers areas other than the emission areas 24 and the first light blocking layer 23A, being disposed on a bottom surface of the blocking substrate 27. As shown in FIG. 6, the first main substrate 21A and the second main substrate 21B correspond to the same blocking substrate 27, and the first light blocking layer 23A of the first main substrate 21A and the second light blocking layer 23B of the second main substrate 21B correspond to the same second light blocking layer 23B at a joint of the first main substrate 21A and the second main

substrate 21B. Accordingly, multiple microLED displays may be joined to become a seamless top emission microLED display 600.

[0077] FIG. 7A to FIG. 13B show top views and cross-sectional views illustrating steps of forming a top emission microLED display according to one embodiment of the present invention. As shown in FIG. 7A and FIG. 7B, a (first) main substrate 21A, which defines an emission area 24, is provided. As shown in FIG. 8A and FIG. 8B, a bottom common electrode layer 28 is formed on a top surface of the (first) main substrate 21A. According to one aspect of the embodiment, the bottom common electrode layer 28 entirely covers the emission area 24 to prevent nonuniform display issue.

[0078] As shown in FIG. 9A and FIG. 9B, microLEDs 12 (e.g., red microLED 12R, green microLED 12G and blue microLED 12B) are disposed on a top surface of the bottom common electrode layer 28 by a bonding technique. As shown in FIG. 10A and FIG. 10B, a (first) light blocking layer 23A is disposed in an area other than the emission area 24 to prevent interference (e.g., color mixing) between adjacent pixels and to enhance contrast.

[0079] As shown in FIG. 11A and FIG. 11B, a light guiding layer 25 is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24. The light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 11B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22. It is noted that the order of forming the (first) light blocking layer 23A (FIG. 10A and FIG. 10B) and forming the light guiding layer 25 (FIG. 11A and FIG. 11B) may be exchanged.

[0080] As shown in FIG. 12A and FIG. 12B, contact holes are formed above the microLEDs 22. Next, as shown in FIG. 13A and FIG. 13B, connecting structures 26 are formed to connect the microLED 22. The connecting structures 26 have the same pattern and the connecting structures 26 in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0081] FIG. 14 schematically shows a side view of a bottom emission micro light-emitting diode (microLED) display 1400. In the embodiment, microLEDs 12 (e.g., red microLED 12R, green microLED 12G and blue microLED 12B) may be disposed above a main substrate 11 by a bonding technique. As the microLEDs 12 emit light downward (as shown by arrows) against the top surface of the main substrate 11, the display 1400 is called a bottom emission microLED display. In the specification, the microLEDs 12 have a size of 1-10 micrometers, which may be decreased or increased according to specific applications or technological development in the future.

[0082] FIG. 15A shows a top view of a bottom emission microLED display 1500 according to a sixth embodiment of the present invention, and FIG. 15B shows a cross-sectional view of FIG. 15A. In the embodiment, microLEDs 22 (e.g., red microLED 22R, green microLED 22G and blue microLED 22B) may be disposed on a top surface of a (first) main substrate 21A. A (first) light blocking layer 23A is disposed between adjacent microLEDs 22 and above the (first) main substrate 21A to prevent interference (e.g., color mixing) between adjacent microLEDs 22 and to enhance

contrast. A top common electrode layer 28 may be disposed above the microLEDs 22 and the light blocking layer 23A.

[0083] The (first) light blocking layer 23A of the embodiment may include black matrix (BM). In the embodiment shown in FIG. 15B, black resin is first formed, followed by adopting photo process and curing process to form the BM (first) light blocking layer 23A. In another embodiment, ink-jet printing technique and curing process are adopted to form the BM (first) light blocking layer 23A.

[0084] The (first) light blocking layer 23A defines emission areas 24, which are not covered with the (first) light blocking layer 23A. In other words, areas other than the emission areas 24 are covered with the (first) light blocking layer 23A. A light guiding layer 25, composed of light guiding material, is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. The light guiding material is transparent with high refractive index. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0085] In the embodiment, the (first) light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 15B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22.

[0086] FIG. 15C shows a cross-sectional view of a bottom emission microLED display 1500 according to a modified sixth embodiment of the present invention. In the embodiment shown in FIG. 15C, the (first) light blocking layer 23A has a thickness less than the light guiding layer 25. Moreover, the (first) light blocking layer 23A and the light guiding layer 25 partially overlap each other, and the (first) light blocking layer 23A is partially covered with the light guiding layer 25. In the embodiment shown in FIG. 15C, a chromium/chromium oxide film is first formed, followed by adopting photo etching technique to form the BM (first) light blocking layer 23A.

[0087] FIG. 15D shows another top view of the bottom emission microLED display 1500 according to the sixth embodiment of the present invention. A connecting structure 26, such as conductive electrode, is disposed between the microLEDs 22 and the main substrate 21A in each emission area 24. The connecting structure 26 may include transparent material (e.g., indium tin oxide), opaque material (e.g., metal) or reflective material. According to one aspect of the embodiment, the connecting structures 26 in the emission areas 24 have the same pattern, which can prevent nonuniform display issue.

[0088] FIG. 16A shows a top view of a bottom emission microLED display 1600 according to a seventh embodiment of the present invention, and FIG. 16B shows a cross-sectional view of FIG. 16A. The seventh embodiment is similar to the sixth embodiment with the exception that, in the seventh embodiment, the (first) light blocking layer 23A is disposed between adjacent pixels (instead of adjacent microLEDs 22) to prevent interference (e.g., color mixing) between adjacent pixels and to enhance contrast.

[0089] The (first) light blocking layer 23A defines emission areas 24, which are not covered with the (first) light blocking layer 23A. In other words, areas other than the emission areas 24 are covered with the (first) light blocking layer 23A. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0090] In the embodiment, the (first) light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 16B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22.

[0091] FIG. 16C shows a cross-sectional view of a bottom emission microLED display 1600 according to a modified seventh embodiment of the present invention. In the embodiment shown in FIG. 16C, the (first) light blocking layer 23A has a thickness less than the light guiding layer 25. Moreover, the (first) light blocking layer 23A and the light guiding layer 25 partially overlap each other, and the (first) light blocking layer 23A is partially covered with the light guiding layer 25.

[0092] FIG. 16D shows another top view of the bottom emission microLED display 1600 according to the seventh embodiment of the present invention. A connecting structure 26, such as conductive electrode, is disposed on a top surface of the microLED 22 in each emission area 24. According to one aspect of the embodiment, the connecting structures 26 in the emission areas 24 have the same pattern and the connecting structures 26 in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0093] FIG. 17A shows a top view of a bottom emission microLED display 1700 according to an eighth embodiment of the present invention, and FIG. 17B shows a cross-sectional view of FIG. 17A. In the embodiment, microLEDs 22 (e.g., red microLED 22R, green microLED 22G and blue microLED 22B) may be disposed above a (first) main substrate 21A. Each microLED 22 corresponds to an emission area 24. In the embodiment, a frame-shaped first light blocking layer 23A surrounds the emission area 24 and is disposed above the (first) main substrate 21A. In the embodiment, a blocking substrate 27 is disposed below the (first) main substrate 21A. A second light blocking layer 23B, which covers areas other than the emission areas 24 and the first light blocking layer 23A, is disposed on a top surface of the blocking substrate 27. The first light blocking layer 23A and the second light blocking layer 23B partially overlap each other. Accordingly, an aperture d1 of the first light blocking layer 23A is different from (e.g., smaller than) an aperture d2 of the second light blocking layer 23B. In another embodiment, the aperture of the first light blocking layer 23A is greater than the aperture of the second light blocking layer 23B. In the embodiment, the first light blocking layer 23A and the second light blocking layer 23B may include BM, and the blocking substrate 27 may include transparent material such as quartz, glass or plastic material.

[0094] A light guiding layer 25, composed of light guiding material, is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0095] In the embodiment, the first light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 17B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22.

[0096] FIG. 17C shows a cross-sectional view of a bottom emission microLED display 1700 according to a modified eighth embodiment of the present invention. In the embodiment shown in FIG. 17C, the first light blocking layer 23A

has a thickness less than the light guiding layer 25. Moreover, the first light blocking layer 23A is partially covered with the light guiding layer 25.

[0097] According to one aspect of the embodiment, the connecting structures 26 (not shown) in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0098] FIG. 18A shows a top view of a bottom emission microLED display 1800 according to a ninth embodiment of the present invention, and FIG. 18B shows a cross-sectional view of FIG. 18A. The ninth embodiment is similar to the eighth embodiment with the exception that, in the ninth embodiment, the first light blocking layer 23A and the second light blocking layer 23B are disposed between adjacent pixels (instead of adjacent microLEDs 22) to prevent interference (e.g., color mixing) between adjacent pixels and to enhance contrast.

[0099] In the embodiment, each pixel (which includes red microLED 22R, green microLED 22G and blue microLED 22B) corresponds to an emission area 24. In the embodiment, a frame-shaped first light blocking layer 23A surrounds the emission area 24 and is disposed above the (first) main substrate 21A. In the embodiment, a second light blocking layer 23B, which covers areas other than the emission areas 24 and the first light blocking layer 23A, is disposed on a top surface of the blocking substrate 27. The first light blocking layer 23A and the second light blocking layer 23B partially overlap each other. Accordingly, an aperture d1 of the first light blocking layer 23A is different from (e.g., smaller than) an aperture d2 of the second light blocking layer 23B. In the embodiment, the first light blocking layer 23A and the second light blocking layer 23B may include BM, and the blocking substrate 27 may include transparent material such as quartz, glass or plastic material.

[0100] A light guiding layer 25, composed of light guiding material, is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24.

[0101] In the embodiment, the first light blocking layer 23A has a thickness greater than the light guiding layer 25. Further, the light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 18B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22.

[0102] FIG. 18C shows a cross-sectional view of a bottom emission microLED display 1800 according to a modified ninth embodiment of the present invention. In the embodiment shown in FIG. 18C, the first light blocking layer 23A has a thickness less than the light guiding layer 25. Moreover, the first light blocking layer 23A is partially covered with the light guiding layer 25.

[0103] According to one aspect of the embodiment, the connecting structures 26 (not shown) in the emission areas 24 have the same pattern and the connecting structures 26 in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0104] FIG. 19 shows a cross-sectional view of a bottom emission microLED display 1900 according to a tenth embodiment of the present invention. In the embodiment, the bottom emission microLED display 1900 may include a first main substrate 21A and a second main substrate 21B, which are disposed at a same level but correspond to distinct microLED displays, respectively. A first light blocking layer

23A is disposed above the first main substrate 21A and the second main substrate 21B. Similar to the ninth embodiment, the bottom emission microLED display 1900 may include a second light blocking layer 23B, which covers areas other than the emission areas 24 and the first light blocking layer 23A, being disposed on a top surface of the blocking substrate 27. As shown in FIG. 19, the first main substrate 21A and the second main substrate 21B correspond to the same blocking substrate 27, and the first light blocking layer 23A of the first main substrate 21A and the second light blocking layer 23B of the second main substrate 21B correspond to the same second light blocking layer 23B at a joint of the first main substrate 21A and the second main substrate 21B. Accordingly, multiple microLED displays may be joined to become a seamless bottom emission microLED display 1900.

[0105] FIG. 20A to FIG. 26B show top views and cross-sectional views illustrating steps of forming a bottom emission microLED display according to one embodiment of the present invention. As shown in FIG. 20A and FIG. 20B, a (first) main substrate 21A, which defines an emission area 24, is provided. As shown in FIG. 21A and FIG. 21B, connecting structures 26 are formed to connect the microLED 22. The connecting structures 26 have the same pattern and the connecting structures 26 in each emission area 24 have the same pattern, which can prevent nonuniform display issue.

[0106] As shown in FIG. 22A and FIG. 22B, microLEDs 12 (e.g., red microLED 12R, green microLED 12G and blue microLED 12B) are disposed on a top surface of the bottom common electrode layer 28 by a bonding technique. As shown in FIG. 23A and FIG. 23B, a (first) light blocking layer 23A is disposed in an area other than the emission area 24 to prevent interference (e.g., color mixing) between adjacent pixels and to enhance contrast.

[0107] As shown in FIG. 24A and FIG. 24B, a light guiding layer 25 is disposed in the emission areas 24 to spread the light emitted by the microLEDs 22. In the embodiment, the light guiding layer 25 is entirely formed in the emission areas 24. The light guiding layer 25 has a thickness greater than the microLEDs 22 as shown in FIG. 24B. In another embodiment, however, the light guiding layer 25 has a thickness less than or equal to the microLEDs 22. It is noted that the order of forming the (first) light blocking layer 23A (FIG. 23A and FIG. 23B) and forming the light guiding layer 25 (FIG. 24A and FIG. 24B) may be exchanged.

[0108] As shown in FIG. 25A and FIG. 25B, contact holes are formed above the microLEDs 22. Next, as shown in FIG. 26A and FIG. 26B, a top common electrode layer 28 is formed above the light guiding layer 25. According to one aspect of the embodiment, the top common electrode layer 28 entirely covers the emission area 24 to prevent nonuniform display issue.

[0109] FIG. 27 shows a cross-sectional view of a bottom emission microLED display 2000 according to an eleventh embodiment of the present invention. Compared to FIG. 19, the bottom emission microLED display 2000 of the present embodiment may include at least one shielding layer 30 for blocking electromagnetic interference (EMI). In one embodiment, the shielding layer 30 may include transparent conductive material such as transparent conductive oxide (e.g., indium tin oxide (ITO), indium zinc oxide (IZO) or aluminum doped Zinc Oxide (AZO)).

[0110] The shielding layer 30 may be disposed between a top surface of the first main substrate 21A and first light blocking layer 23A. The shielding layer 30 may be electrically insulated from the top common electrode layer 28 by an insulating layer 29, and may be electrically insulated from the connecting structure 26 by an insulating layer 31. Similarly, the shielding layer 30 may be disposed between a top surface of the second main substrate 21B and first light blocking layer 23A. The shielding layer 30 may be electrically insulated from the top common electrode layer 28 by an insulating layer 29, and may be electrically insulated from the connecting structure 26 by an insulating layer 31. The shielding layer 30 may be disposed between a top surface of the blocking substrate 27 and the second light blocking layer 23B. Generally speaking, the shielding layer 30 may be disposed in one or more areas mentioned above.

[0111] The shielding layer 30 may be adaptable to a top emission microLED display. FIG. 28 shows a cross-sectional view of a top emission microLED display 2100 according to a twelfth embodiment of the present invention. Compared to FIG. 6, the top emission microLED display 2100 of the present embodiment may include at least one shielding layer 30 for blocking electromagnetic interference (EMI). In one embodiment, the shielding layer 30 may include transparent conductive material such as transparent conductive oxide (e.g., indium tin oxide (ITO), indium zinc oxide (IZO) or aluminum doped Zinc Oxide (AZO)). In the embodiment, the shielding layer 30 may be disposed between a bottom surface of the blocking substrate 27 and the second light blocking layer 23B.

[0112] FIG. 29 shows a cross-sectional view of a bottom emission microLED display 2900 according to a thirteenth embodiment of the present invention. Compared to FIG. 15B, the bottom emission microLED display 2900 of the present embodiment may include an anti-floodlight layer 32 disposed on a bottom surface of the first main substrate 21A and between adjacent microLEDs 22. In other words, the anti-floodlight layer 32 may be disposed on the first main substrate 21A opposite the (first) light blocking layer 23A. FIG. 30 shows a cross-sectional view of a bottom emission microLED display 2900 according to a modified thirteenth embodiment of the present invention. Compared to FIG. 15C, the bottom emission microLED display 2900 of the present embodiment may include an anti-floodlight layer 32 disposed on a bottom surface of the first main substrate 21A and between adjacent microLEDs 22. In other words, the anti-floodlight layer 32 may be disposed on the first main substrate 21A opposite the (first) light blocking layer 23A.

[0113] After the light emitted by the microLEDs 22 enters the first main substrate 21A, some of the generated light passes through the first main substrate 21A, while other of the generated light laterally diffuses in the first main substrate 21A due to total reflection, which may interfere with adjacent microLED 22 or pixel to result in floodlight issue. The anti-floodlight layer 32 of the embodiment may absorb lateral diffused light and effectively avoid floodlight issue.

[0114] The anti-floodlight layer 32 of the embodiment may include BM. In one example, a chromium/chromium oxide film is first formed, followed by adopting photo etching technique to form the BM anti-floodlight layer 32. In another example, black resin is first formed, followed by adopting photo process and curing process to form the BM anti-floodlight layer 32. In a further example, ink-jet printing technique and curing process are adopted to form the BM

anti-floodlight layer 32. The anti-floodlight layer 32 may be directly formed on the first main substrate 21A, or may be first formed on another substrate, which is then attached on the first main substrate 21A.

[0115] As discussed above, the anti-floodlight layer 32 may be disposed between adjacent microLEDs 22. However, the anti-floodlight layer 32 may be disposed between adjacent pixels. FIG. 31 shows a cross-sectional view of a bottom emission microLED display 3100 according to a fourteenth embodiment of the present invention. Compared to the seventh embodiment shown in FIG. 16B, the bottom emission microLED display 3100 of the present embodiment may include an anti-floodlight layer 32 disposed on a bottom surface of the first main substrate 21A and between adjacent pixels. In other words, the anti-floodlight layer 32 may be disposed on the first main substrate 21A opposite the (first) light blocking layer 23A. FIG. 32 shows a cross-sectional view of a bottom emission microLED display 3100 according to a modified fourteenth embodiment of the present invention. Compared to the modified seventh embodiment shown in FIG. 16C, the bottom emission microLED display 3100 of the present embodiment may include an anti-floodlight layer 32 disposed on a bottom surface of the first main substrate 21A and between adjacent pixels. In other words, the anti-floodlight layer 32 may be disposed on the first main substrate 21A opposite the (first) light blocking layer 23A.

[0116] Although specific embodiments have been illustrated and described, it will be appreciated by those skilled in the art that various modifications may be made without departing from the scope of the present invention, which is intended to be limited solely by the appended claims.

What is claimed is:

1. A method of forming a top emission microLED display, comprising:
 - providing a first main substrate;
 - forming a plurality of microLEDs above the first main substrate;
 - forming a first light blocking layer above the first main substrate to define a plurality of emission areas;
 - forming a light guiding layer in the emission areas; and
 - forming a plurality of connecting structures disposed in the emission areas respectively and electrically connected with the microLEDs.
2. The method of claim 1, wherein the connecting structures have a same pattern.
3. The method of claim 1, wherein the connecting structures comprise transparent material.
4. The method of claim 1, wherein the connecting structures comprise opaque material.
5. The method of claim 1, before forming the microLEDs, further comprising a step of entirely forming a conductive layer in the emission areas of the first main substrate.
6. The method of claim 1, before forming the connecting structures, further comprising a step of forming contact holes above the microLEDs.
7. The method of claim 1, wherein the first light blocking layer comprises black matrix.
8. The method of claim 1, wherein a red microLED, a green microLED and a blue microLED in the emission area respectively correspond to the connecting structures with a same pattern.
9. The method of claim 1, wherein the step of forming the first light blocking layer comprises:

forming black resin; and

treating the black resin by photo process and curing process to form the first light blocking layer with black matrix.

10. The method of claim 1, wherein the step of forming the first light blocking layer comprises:

using ink-jet printing technique and curing process to form the first light blocking layer with black matrix.

11. The method of claim 1, wherein the step of forming the first light blocking layer comprises:

forming a chromium/chromium oxide film; and

treating the chromium/chromium oxide film by photo etching technique to form the first light blocking layer with black matrix.

12. A method of forming a bottom emission microLED display, comprising:

providing a first main substrate;

forming a plurality of connecting structures in a plurality of emission areas;

forming a plurality of microLEDs above the connecting structures;

forming a first light blocking layer above the first main substrate to define the emission areas covering the connecting structures; and

forming a light guiding layer in the emission areas.

13. The method of claim 12, wherein the connecting structures have a same pattern.

14. The method of claim 12, wherein the connecting structures comprise transparent material.

15. The method of claim 12, wherein the connecting structures comprise opaque material.

16. The method of claim 12, after forming the light guiding layer or the first light blocking layer, further comprising a step of entirely forming a conductive layer in the emission areas of the first main substrate.

17. The method of claim 16, before forming the conductive layer, further comprising a step of forming contact holes above the microLEDs.

18. The method of claim 12, wherein the first light blocking layer comprises black matrix.

19. The method of claim 12, wherein a red microLED, a green microLED and a blue microLED in the emission area respectively correspond to the connecting structures with a same pattern.

20. The method of claim 12, wherein the step of forming the first light blocking layer comprises:

forming black resin; and

treating the black resin by photo process and curing process to form the first light blocking layer with black matrix.

21. The method of claim 12, wherein the step of forming the first light blocking layer comprises:

using ink-jet printing technique and curing process to form the first light blocking layer with black matrix.

22. The method of claim 12, wherein the step of forming the first light blocking layer comprises:

forming a chromium/chromium oxide film; and

treating the chromium/chromium oxide film by photo etching technique to form the first light blocking layer with black matrix.

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专利名称(译)	顶部发射微LED显示器和底部发射微LED显示器及其形成方法		
公开(公告)号	US20200083281A1	公开(公告)日	2020-03-12
申请号	US16/153604	申请日	2018-10-05
[标]发明人	WU BIING SENG WU CHAO WEN		
发明人	WU, BIING-SENG WU, CHAO-WEN		
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CPC分类号	H01L33/36 H01L33/62 G09G3/2003 G03F7/0007 H01L27/156 H01L25/0753 H01L33/58 G09G3/32		
外部链接	Espacenet USPTO		

摘要(译)

microLED显示器包括第一主基板，设置在第一主基板上方的microLED，设置在第一主基板上以限定发射区域的第一光阻挡层，设置在发射区域中的导光层以及设置的多个连接结构 分别在发射区域内并与microLED电连接。

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